

DS3170DK DS3/E3 Single-Chip Transceiver Design Kit

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GENERAL DESCRIPTION

The DS3170DK is a fully integrated design kit for the DS3170 DS3/E3 single-chip transceiver (SCT). This design kit contains all the necessary circuitry to evaluate the DS3170 in all modes of operation. The design kit also includes an on-board microprocessor to run real-time code for further part evaluation.

DESIGN KIT CONTENTS

DS3170DK Board

Download:

ChipView Software

DS3170DK.DEF Definition File

DS3170DK Data Sheet

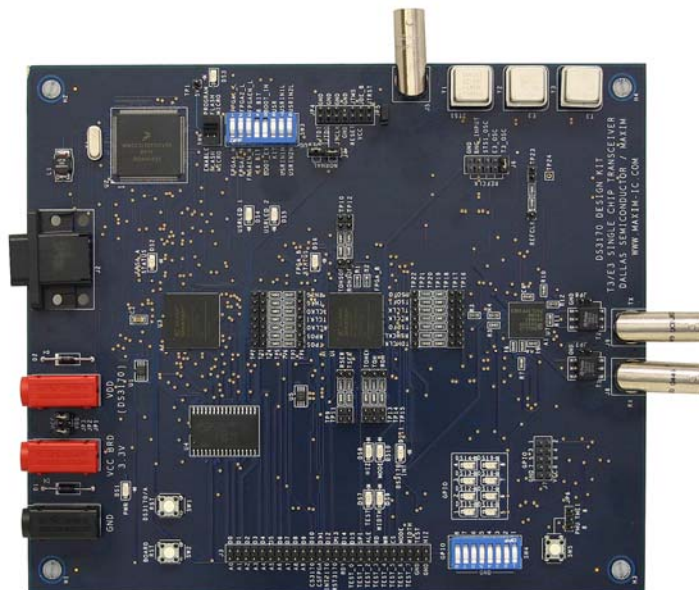
ORDERING INFORMATION

PART	DESCRIPTION
DS3170DK	Design Kit for the DS3170 DS3/E3 Single-Chip Transceiver

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FEATURES

- Expedites New Designs by Eliminating First-Pass Prototyping
- Demonstrates Key Functions of the DS3170 DS3/E3 Single-Chip Transceiver (SCT)
- Includes DS3170 Single-Chip Transceiver (SCT), Transformers, 75Ω BNC, and Termination Passives
- Interfaces with Any PC with an RS-232 Serial Interface
- High Level Windows®-Based Software Provides Visual Access to All Registers
- Software Controlled (Register) Mapped Configuration Switches Facilitate Real-Time Clock and Signal Routing
- Precision Test Points for All Clocks and Signals
- On-Board DS3 and E3 Crystal Oscillators for Stable Clock Generation
- Easy-to-Read Silkscreen Labels Identify the Signals Associated with All Connectors, Jumpers, and LEDs



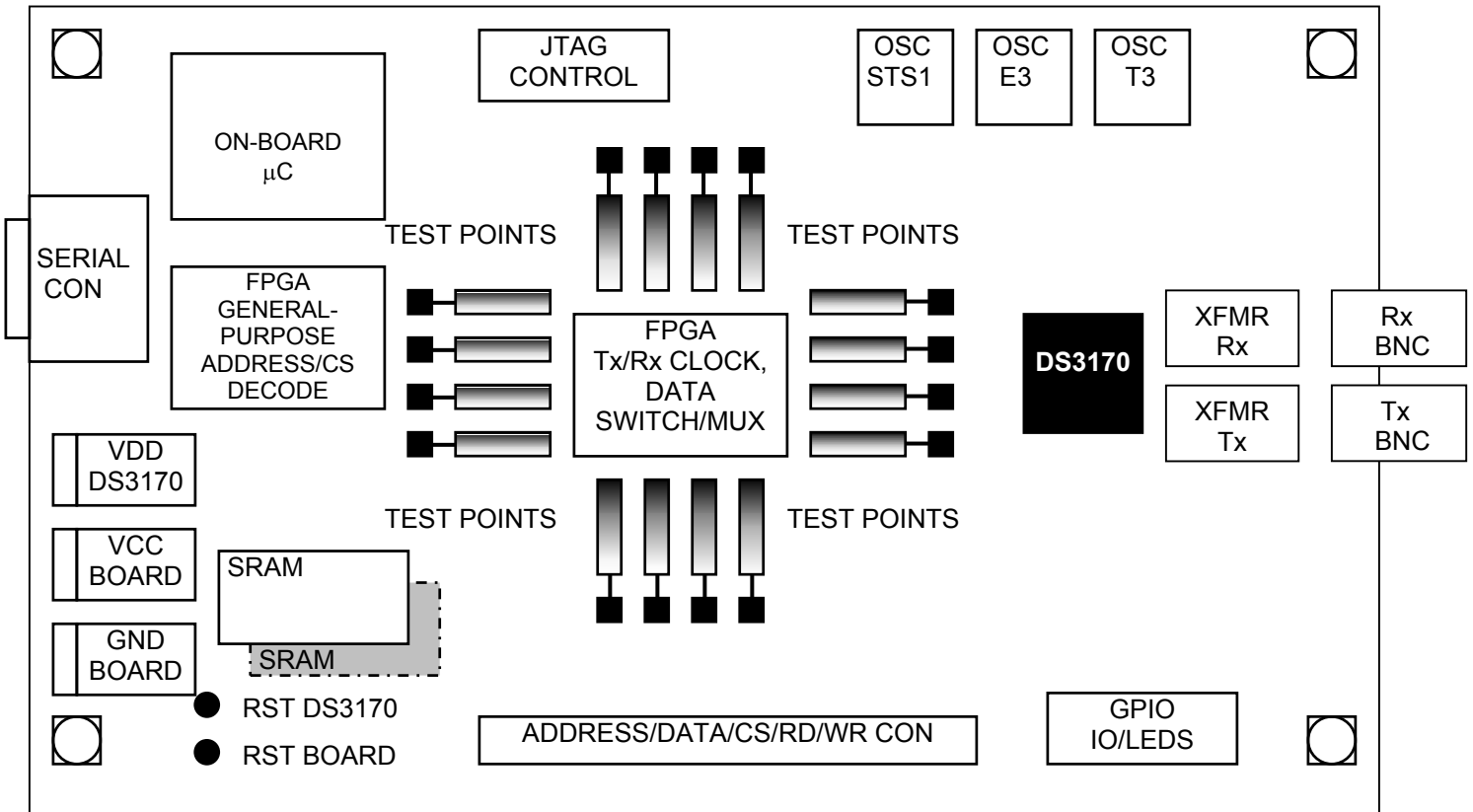
COMPONENT LIST

DESIGNATION	QTY	DESCRIPTION	SUPPLIER	PART NUMBER
C1, C4, C5, C10, C14, C15, C18, C19, C21, C24, C25–C32, C36–C38, C39–C44, C47–C49, C50, C52–C56, C59–C61, C66, C68, C70, C73, C74	44	0.1 μ F 20%, 16V X7R ceramic capacitors (0603)	AVX	0603YC104MAT
C2, C3, C16, C17, C20, C22, C23, C33, C34, C51, C57, C69, C75	13	1 μ F 10%, 16V ceramic capacitors (1206)	Panasonic	ECJ-3YB1C105K
C6, C62, C65	3	0.001 μ F 10%, 50V ceramic capacitors (0603)	Panasonic	ECJ-1VB1H102K
C7, C8, C9, C11, C35, C58, C76	7	68 μ F 20%, 16V tantalum capacitors (D case)	Panasonic	ECS-T1CD686R
C12, C13	2	10pF 5%, 50V ceramic capacitors (tall case)	Phycomp	1206CG100J9B200
C45, C46	2	10,000pF 10%, 16V ceramic capacitors (0603)	Panasonic	ECJ-1VB1C103K
C63, C64, C67	3	0.01 μ F 10%, 50V X7R ceramic capacitors (0603)	AVX	06035C103KAT
C71, C72	2	56,000pF 10%, 16V ceramic capacitors (0603)	Panasonic	ECJ-1VB1C563K
D1, D2	2	1A 50V general-purpose silicon diodes	General Semiconductor	1N4001
DS1, DS2, DS6–DS10	7	LED, green, SMD	Panasonic	LN1351C
DS3, DS4, DS5, DS11–DS19	12	LED, red, SMD	Panasonic	LN1251C
J1, PWR_CONNBAN1	2	Banana plug sockets (horizontal, black)	Mouser Electronics	164-6218
J2	1	DB9 right-angle connector (long case)	AMP	747459-1
J3	1	50-pin, dual-row, vertical terminal strip	Samtec	TSW-125-07-T-D
J4	1	100-mils 4-position jumper	Samtec	NA
J5	1	50 Ω BNC connector (5-pin right-angle header)	Trompeter	CBJR220
J6, J7	2	Terminal strip, 10-pin, dual row, vertical	Samtec	NA
J8, J9	2	75 Ω BNC connectors (5-pin right-angle)	Trompeter	UCBJR220
JP1, JP2, JP3, JP5, JP7, JP8	6	2-pin headers, 0.100" centerline (vertical)	Samtec	TSW-102-07-T-S
JP4	1	14-pin connector (dual row, vertical)	Samtec	NA
JP6	1	100-mils 3-position jumper	Samtec	NA
L1	1	1.0 μ H 20% 2-pin surface-mount inductor	Coiltronics	UP1B-1R0
PWR_CONNBAN2	1	Banana plug socket (horizontal, red)	Mouser Electronics	164-6219

DESIGNATION	QTY	DESCRIPTION	SUPPLIER	PART NUMBER
R1–R4, R12, R42, R43, R54–R56, R59, R63, R68, R69, R70, R73, R74, R83, R93, R107	20	150Ω 1%, 1/16W resistors (0603)	Panasonic	ERJ-3EKF1500V
R5–R8, R10, R15, R51, R57, R62, R71, R81, R85, R92, R94, R95, R100, R101, R103–R106, R109	22	33Ω 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ330V
R9, R11, R16, R22, R30, R32, R38, R46, R60, R61, R64, R65, R72, R77–R80, R89, R90, R91, R96	22	330Ω 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ331V
R13	1	1.0MΩ 5%, 1/16W resistor (0603)	Panasonic	ERJ-3GEYJ105V
R14, R17–R21, R23–R29, R31, R33–R37, R39, R40, R41, R44, R45, R47, R48, R49, R52, R53, R58, R67, R75, R76, R82, R86, R87, R98, R99, R102, R108, R110	41	10kΩ 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ103V
R50	1	1.0kΩ 5%, 1/16W resistor (0603)	Panasonic	ERJ-3GEYJ102V
R66, R88, R97	3	0Ω 1%, 1/16W resistors (0603)	AVX	CJ10-000F
R84	1	51.1Ω 1%, 1/16W resistor (0603)	Panasonic	ERJ-3EKF51R1V
SW1, SW2, SW5	3	4-pin single-pole switch MOM	Panasonic	EVQPAE04M
SW3, SW4	2	8-position switch, 16-pin DIP, low profile	AMP	435668-7
SW6	1	Slide switch (DPDT) 6-pin through-hole	Tyco	SSA22
T1, T2	2	1:2 XFMR T3/E3/STS-1 (industrial)	Pulse	T3012
TP1–TP24	24	Test points, compensated, 3pF, 953Ω, 3 plated holes	NA	KIT1
U1, U5	2	8-pin power-μMAX (1.8V or Adj)	Maxim	MAX1792EUA18
U2	1	M-CORE 32-bit microcontroller	Motorola	MMC2107
U3, U6	2	Spartan-II E 200K gate, 1.8V FPGA, 256 PIN BGA	Xilinx	XC2S200E-6FT256C
U4, U11	2	128K x 8 SRAM	Cypress	CY62128V
U7	1	DS3/E3 SCT 100-pin CSBGA (11mm x 11mm)	Dallas Semiconductor	DS3170
U8	1	3.3V RS-232 20-pin SO	Maxim	MAX3233EEWP
U9, U14, U16–U20, U23	8	High-speed buffer	Fairchild	NC7SZ86

DESIGNATION	QTY	DESCRIPTION	SUPPLIER	PART NUMBER
U10, U12	2	2Mb flash-based configuration memory	Xilinx	XCF02SV020C
U13	1	Quad 2-input NAND gate 14-pin SO	Toshiba	TC74HC00AFN
U15, U21, U24	3	Hex inverter, SO	Toshiba	TC74HC04AFN
U22	1	SOT switch debouncer	Maxim	MAX6816
X1	1	8.0MHz low-profile crystal	Dove Electronic	EC1-8.000M
Y1	1	3.3V 51.840MHz oscillator, crystal clock	SaRonix	NTH089AA3-51.840
Y2	1	3.3V 34.368MHz oscillator, crystal clock	SaRonix	NTH089AA3-34.368
Y3	1	3.3V 44.736MHz oscillator, crystal clock	SaRonix	NTH089AA3-44.736

BOARD FLOORPLAN



BASIC OPERATION

This design kit relies upon several supporting files, which are available for downloading on our website at www.maxim-ic.com/telecom. See the DS3170DK QuickView page for files.

The support files are used with an evaluation program called ChipView with is available for download at www.maxim-ic.com/telecom.

HARDWARE CONFIGURATION

Quick Start (Hardware Settings)

- For single power-supply operation, short jumpers JP1-JP3. This connects VDD of the DS3170 to the board VCC.
- Ensure that *PROGRAM FLASH MICRO* is selected (SW6). DS3 should not be on.
- Connect reference clock. See [Table 1](#).
- DIP switches (SW3) can be in either the ON or OFF position depending on the desired configuration. See [Table 6](#).
- Connect serial cable from DS3170DK (J2) to PC.
- Supply 3.3V to the banana-plug receptacles marked GND and VCC_3.3V.

Reference Clock Configuration

The reference clock for the DS3170 (SCT) can be configured a number of ways depending on the application's need. This is done by shorting the REFCLK signal on J6 to the signal inputs, which are also connected to J6.

Table 1: Reference Clock Configuration

REFERENCE CLOCK	DESCRIPTION
GND	Short pins J6.1 and J6.2 together. Open all other pins on J6.
BNC Input	Short pins J6.3 and J6.4 together. Open all other pins on J6.
STS1 OSC	Short pins J6.5 and J6.6 together. Open all other pins on J6.
E3 OSC	Short pins J6.7 and J6.8 together. Open all other pins on J6.
T3 OSC	Short pins J6.9 and J6.10 together. Open all other pins on J6.

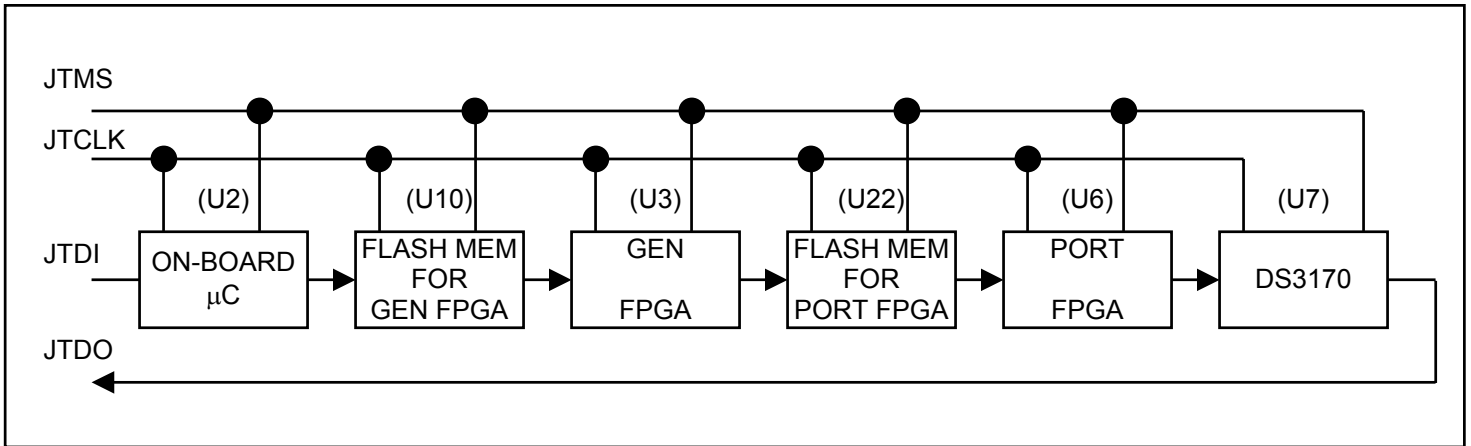
JTAG Configuration

The JTAG chain is controlled by the following connectors: J4, JP4, and JP5. Depending on the function, such as programming the internal microcontroller flash or performing boundary scan operations, the three connectors can be configured to accomplish the desired task. For information on programming the internal flash of the microcontroller, refer to the microcontroller user manual and board schematic.

For most purposes, having the complete JTAG chain is sufficient. [Figure 1](#) shows the complete chain as well as what order the devices will appear during boundary scan. To set up this configuration, perform the following:

- Connect JTDI to JP4.1
- Connect JTDO to JP4.3
- Connect JTMS to JP4.10
- Connect JCLK to JP4.5
- Connect J4.1 to J4.2
- Connect J4.3 to J4.4
- Connect JP5.1 to JP5.2

Figure 1. JTAG Chain



Address/Data BUS Connector

The DS3170DK has a connector (J3) to monitor all local bus activity for the design kit. All the signals can be captured with a high-impedance probe and displayed on an oscilloscope or logic analyzer. **Note:** If FPGA_ENABLE (SW3.3) is logic 0, the on-board microcontroller will no longer drive any data onto the local bus. Therefore, the user can now connect the local bus of the DS3170 into another system without making any modifications to the hardware. See [Table 2](#) for specific pin information for connector J3.

Table 2. Address/Data Connector

PIN NUM	PIN NAME	DESCRIPTION	PIN NUM	PIN NAME	DESCRIPTION
1	A0	Local Address Bit 0	2	D0	Local Data Bit 0
3	A1	Local Address Bit 1	4	D1	Local Data Bit 1
5	A2	Local Address Bit 2	6	D2	Local Data Bit 2
7	A3	Local Address Bit 3	8	D3	Local Data Bit 3
9	A4	Local Address Bit 4	10	D4	Local Data Bit 4
11	A5	Local Address Bit 5	12	D5	Local Data Bit 5
13	A6	Local Address Bit 6	14	D6	Local Data Bit 6
15	A7	Local Address Bit 7	16	D7	Local Data Bit 7
17	A8	Local Address Bit 8	18	D8	Local Data Bit 8
19	A9	Local Address Bit 9	20	D9	Local Data Bit 9
21	CS3170	Chip Select DS3170	22	D10	Local Data Bit 10
23	CSFPGA	Chip Select Port FPGA	24	D11	Local Data Bit 11
25	INT3170	INT PIN DS3170	26	D12	Local Data Bit 12
27	RST3170	RST PIN DS3170	28	D13	Local Data Bit 13
29	RDY	Ready Handshake DS3170	30	D14	Local Data Bit 14
31	TEST0	Generic I/O Bit 0	32	D15	Local Data Bit 15
33	TEST1	Generic I/O Bit 1	34	SPI	DS3170 Serial/Parallel Bus Mode
35	TEST2	Generic I/O Bit 2	36	ALE	Address Latch Enable
37	TEST3	Generic I/O Bit 3	38	RD_DS	Read (Intel)/Data Strobe (MOT)
39	TEST4	Generic I/O Bit 4	40	WR_W/R	Write (Intel)/Write_READ (MOT)
41	TEST5	Generic I/O Bit 5	42	CS_OUT	Programmable CS_OUT Pin
43	TEST6	Generic I/O Bit 6	44	MODE	Mot/Intel Mode
45	TEST7	Generic I/O Bit 7	46	WIDTH	Data Bus Width
47	GND	GND	48	TEST	Test Enable (Active Low)
49	GND	GND	50	HIZ	High Impedance (Active Low)

High Impedance and Compensated Test Points

The test points for all the clock and data lines are unique for this board such that each test point listed in [Table 3](#) have a relative high-impedance pin and a compensated pin. The compensated pin is part of a (20:1) voltage divider that when used with the standard 50Ω load of an oscilloscope provides a very clean signal. If you are making critical timing and or slew rate measurements, the compensated test points are very useful. [Figure 2](#) shows the relationship between the high-impedance and compensated test point pins.

Figure 2. Test Point Logical and Physical View

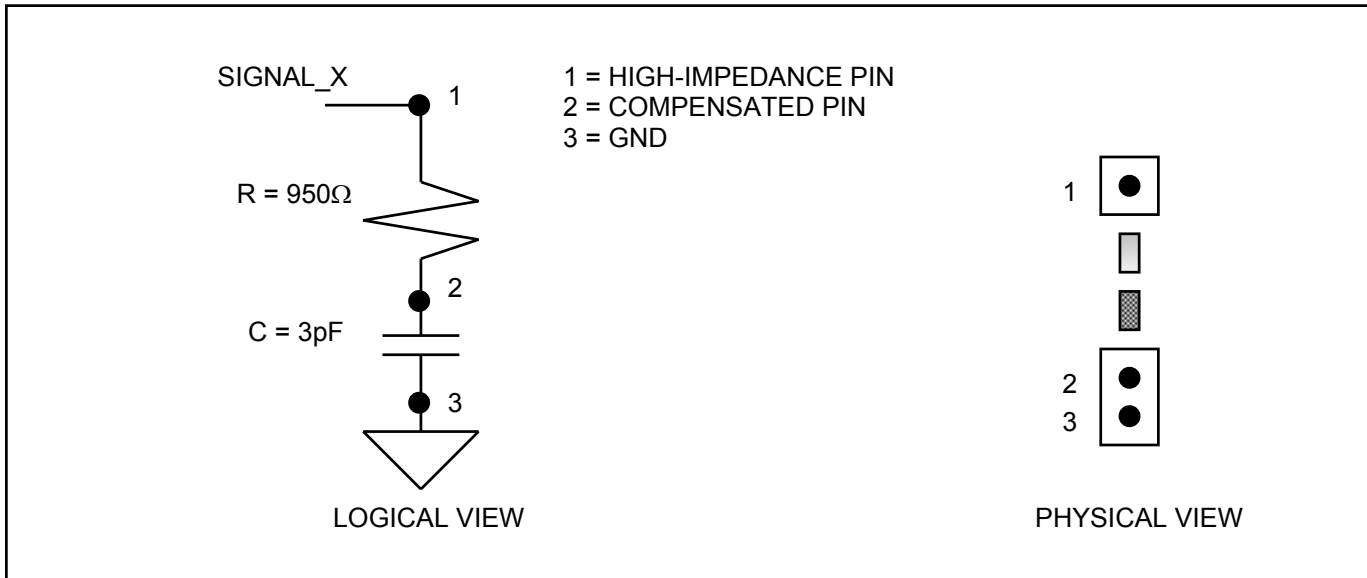


Table 3. Test Points

REF DES	SIGNAL NAME	REF DES	SIGNAL NAME
TP5	TCLKI	TP7	TNEG
TP6	TCLKO	TP8	RNEG
TP4	RCLKO	TP2	TPOS
TP20	TLCLK	TP3	RPOS
TP19	RLCLK	TP11	TSER
TP10	TOHSOF	TP9	RSER
TP12	ROHSOF	TP13	TOHEN
TP16	TOHCLK	TP14	TOH
TP17	ROHCLK	TP15	ROH
TP19	TSOFO	TP23	REFCLK
TP22	RSOFO	TP21	TSOFI

General Purpose Input/Output for DS3170

The DS3170 SCT has an 8-bit port that can be bit configured as either general-purpose I/O or specific alarms, a TEMI input, or PMU input. Refer to the DS3170 data sheet for specific questions about the operation of the DS3170 GPIO port.

Each GPIO pin has two types of inputs and an LED for easy identification of the pin's state. The first input type for the GPIO port is an 8-bit switch (SW4). Each pin on SW4 corresponds to the bit in the GPIO. When the switch is in the "On" position, the pin for the switch is grounded and provides logic 0 to the port. When the switch is in the "Off" position, the pin for the switch floats to VDD and provides logic 1 to the port.

The second input type for the GPIO port is a straight 10-pin header (J7). This can be simply a monitoring pin for the GPIO port or used as input stimulus. **Note:** If you plan to drive a bit to a value other than GND, the GPIO bit in SW4 must be in the "Off" position. See the DS3170DK schematic for questions on the connection of the GPIO port.

[Table 4](#) provides a description of pin out of SW4 and J7.

Table 4. GPIO Header and Switch Pinout

PIN NUMBER		PIN NAME
SW4.1	J7.1	GPIO Bit 1
SW4.2	J7.2	GPIO Bit 2
SW4.3	J7.3	GPIO Bit 3
SW4.4	J7.4	GPIO Bit 4
SW4.5	J7.5	GPIO Bit 5
SW4.6	J7.6	GPIO Bit 6
SW4.7	J7.7	GPIO Bit 7
SW4.8	J7.8	GPIO Bit 8

TEMI and PMU Inputs

GPIO Bit 6 and GPIO Bit 8 can be configured to be the TEMI and PMU inputs respectively. A pushbutton (SW5) and 3-position jumper (JP6) are available to provide a glitch-free input to either of these inputs. **Note:** When using the pushbutton (SW5) and 3-position jumper (JP6) as an input to the GPIO pins, you must have the appropriate switch in SW4 in the "Off" position.

Table 5. TEMI and PMU Configuration

SIGNAL NAME	SETUP PROCEDURE
TEMI	Set SW4.6 to the "Off" position
	Short (Jumper) JP6.3 and JP2
PMU	Set SW4.8 to the "Off" position
	Short (Jumper) JP6.1 and JP2

User Input Switch (SW3)

SW3 is an 8-pin DIP switch that controls the function of the on-board microcontroller and the two on-board FPGAs, and offers a number of generic inputs for user programs.

Table 6. User Input Switch Pinout

PIN	NAME	FUNCTION
1	FPGA INPUT 1	Generic Input-Only Pin to the General-Purpose FPGA. Value of pin is copied to general-purpose register XXXXXXXX. Can be used for user programs. This pin has no effect if FPGA ENABLE is logic 0.
2	FPGA INPUT 2	Generic Input-Only Pin to the General-Purpose FPGA. Value of pin is copied to general-purpose register XXXXXXXX. Can be used for user programs. This pin has no effect if FPGA ENABLE is logic 0.
3	FPGA ENABLE	Input-Only Pin to the General-Purpose FPGA (U3). When this pin is logic 1 (SW3.3 is OFF), the FPGA is enabled and will transfer data from the DS3170 and FPGA as directed from the on-board microcontroller. When this pin is logic 0 (SW3.3 is ON), the FPGA is disabled. All inputs and outputs to the DS3170 and port FPGA are tri-stated. Note: This pin does not cause a hardware enable for the PORT FGPA.
4	DATA BUS SELECT	Input-Only Pin to the General-Purpose FPGA (U3). When this pin is logic 1 (SW3.4 is OFF), the DS3170 and the port FPGA are set up such that they use the 16-bit bus from the on-board microcontroller. When this pin is logic 0 (SW3.4 is ON), the DS3170 and the port FPGA are set up such that they use the 8-bit bus from the on-board microcontroller. This pin has no effect if FPGA ENABLE is logic 0.
5	BOOT SEL	Input-Only Pin to the On-Board Microcontroller. When this pin is logic 1 (SW3.5 is OFF), the on-board microcontroller loads the firmware from an external source rather than the internal flash bank. When this pin is logic 0 (SW3.5 is ON), the microcontroller loads the firmware from the internal flash bank. If you choose to load code from an external source, refer to the user manual for the on-board microcontroller (U2) to ensure that all the timing and data are correct to run this program. This option should only be used by the advanced user.
6	KIT	Input-Only Pin to the On-Board Microcontroller. Not implemented with the firmware shipped from Dallas Semiconductor. This pin can be used by a user program.
7	USER INPUT 1	Input/Output Pin to the General-Purpose FPGA (U3). This pin has an LED (DS4) to track the value of this signal. This pin has no effect if FPGA ENABLE is logic 0. Note: If you choose to use this as an output, USER INPUT 1 (SW3.7) must be in the off position.
8	USER INPUT 2	Input/Output Pin to the General-Purpose FPGA (U3). This pin has an LED (DS5) to track the value of this signal. This pin has no effect if FPGA ENABLE is logic 0. Note: If you choose to use this as an output, USER INPUT 1 (SW3.8) must be in the off position.

SOFTWARE CONFIGURATION

Quick Start (Software—ChipView)

- Perform steps in the Quick Start (Hardware Settings).
- Load ChipView software.
- Select COM port.
- Select Register View.
- From the Programs menu, launch the host application named ChipView.EXE. If the default installation options were used, click the Start button on the Windows toolbar and select Programs → ChipView → ChipView.
- Load the DS3170DK.DEF file.
- Make sure that all the register settings are correct for the proper function desired for the DS3170DK.
- Refer to the DS3170 data sheet for all questions pertaining to device functionality.

MEMORY MAP

The on-board microcontroller is configured to start the user address space at 0x81000000. All offsets given in [Table 7](#) are relative to the beginning of the user address space. All device registers can be easily modified using ChipView.EXE host-based user-interface software.

Table 7. Relative Address Map

REF DES	DEVICE	OFFSET
U3	General-purpose FPGA	0x0000
U6	FPGA Tx/Rx clock, data switch/mux	0x1000
U7	DS3170 DS3/E3 single-chip transceiver	0x2000

Table 8. General-Purpose Memory Map

OFFSET	REGISTER NAME	TYPE	DESCRIPTION
0x00	BRDID	Read Only	Board ID
0x02	DSIDH	Read Only	Dallas Extended ID Upper Nibble
0x03	DSIDM	Read Only	Dallas Extended ID Middle Nibble
0x04	DSIDL	Read Only	Dallas Extended ID Lower Nibble
0x05	BRDREV	Read Only	Board Rev
0x06	ASMREV	Read Only	Assembly Rev
0x07	FPGAREV	Read Only	FPGA Firmware Rev
0x08	CTRL1	Control	Control Reg #1

ID REGISTERS

BID: BOARD ID (Offset=0X0000)

BID is read only with a value of 0xD.

XBIDH: HIGH NIBBLE EXTENDED BOARD ID (Offset=0X0002)

XBIDH is read only with a value of 0x00.

XBIDM: MIDDLE NIBBLE EXTENDED BOARD ID (Offset=0X0003)

XBIDM is read only with a value of 0x07.

XBIDL: LOW NIBBLE EXTENDED BOARD ID (Offset=0X0004)

XBIDL is read only with a value of 0x00.

BREV: BOARD FAB REVISION (Offset=0X0005)

BREV is read only and displays the current fab revision.

AREV: BOARD ASSEMBLY REVISION (Offset=0X0006)

AREV is read only and displays the current assembly revision.

PREV: PLD REVISION (Offset=0X0007)

PREV is read only and displays the current PLD firmware revision.

CONTROL REGISTERS

Register Name: **CTRL1**

Register Description: **Control Register 1**

Register Offset: **0x0008**

Bit #	7	6	5	4	3	2	1	0
Name	SPI_CPOL	SPI_CPHA	SPI_SWAP	SPI	HIZ	WIDTH	MOT	MUX
Default	0	0	0	0	1	0	0	0

Bit 7: SPI_CPOL: This bit controls the SPI Interface Clock Polarity pin, which is muxed with the D7 pin on the DS3170. Bit 7 is only active when bit 4 (SPI) is a logic 1. Refer to the DS3170 data sheet for pin operation.

Bit 6: SPI_CPHA: This bit controls the SPI Interface Clock Phase pin, which is muxed with the D6 pin on the DS3170. Bit 6 is only active when Bit 4 (SPI) is a logic 1. Refer to the DS3170 data sheet for pin operation.

Bit 5: SPI_SWAP: This bit controls the SPI Interface Bit Order Swap pin, which is muxed with the D5 pin on the DS3170. Bit 5 is only active when Bit 4 (SPI) is a logic 1. Refer to the DS3170 data sheet for pin operation.

Bit 4: SPI: This bit controls the SPI Bus Mode bit.
0 = parallel bus mode
1 = SPI bus mode

Bit 3: HIZ: This bit controls the high-impedance test-enable bit (active low). This signal puts all the digital outputs and bidirectional outputs to a high-impedance state when pulled low and also when the JTRST is pulled low. For normal operation, keep it as a logic 1.

Bit 2: WIDTH: This bit controls the databus width pin for parallel bus mode.
0 = 8-bit parallel mode
1 = 16-bit parallel mode

Bit 1: MOT: This bit controls the MODE pin for the DS3170.
0 = RD/WR strobe mode (Intel)
1 = DS strobe mode (Motorola)

Bit 0: MUX: This bit determines if the ALE pin on the DS3170 is in mux mode or nonmux mode (constantly high).
0 = nonmux mode
1 = mux mode

Register Name: **CTRL2**Register Description: **Control Register 2–Line IO**Register Offset: **0x0009**

Bit #	7	6	5	4	3	2	1	0
Name	RNEG3	RNEG2	RNEG1	RNEG0	RPOS3	RPOS2	RPOS1	RPOS0
Default	0	0	0	0	1	0	0	0

Bits 7 to 4: RNEGx: These bits control the source of the RNEG signal.**Bits 3 to 0: RPOSx:** These bits control the source of the RPOS signal.

RPOSx	DESCRIPTION
0x00	HI-Z
0x01	TPOS
0x02	T3 OSC
0x03	E3 OSC
0x04	STS1 OSC
0x05	BNC_INPUT
0x06	Logic 0
0x07	Logic 1
0x08–0xFF	HI-Z

RNEGx	DESCRIPTION
0X00	HI-Z
0X01	TNEG
0X02	T3 OSC
0X03	E3 OSC
0X04	STS1 OSC
0X05	BNC_INPUT
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

Register Name: **CTRL3**Register Description: **Control Register 3–Line RCLK**Register Offset: **0x000A**

Bit #	7	6	5	4	3	2	1	0
Name	—	—	—	—	RLCLK3	RLCLK2	RLCLK1	RLCLK0
Default	0	0	0	0	0	0	0	0

Bits 7 to 4: These bits are unused.**Bits 3 to 0: RLCLKx:** These bits control the source of the RLCLK signal.

RLCLKx	DESCRIPTION
0X00	HI-Z
0X01	TLCLK
0X02	T3 OSC
0X03	E3 OSC
0X04	STS1 OSC
0X05	BNC_INPUT
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

Register Name: **CTRL4**Register Description: **Control Register 4 Overhead Interface**Register Offset: **0x000B**

Bit #	7	6	5	4	3	2	1	0
Name	TOHEN3	TOHEN2	TOHEN1	TOHEN0	TOH3	TOH2	TOH1	TOH0
Default	0	0	0	0	0	0	0	0

Bits 7 to 4: TOHENx: These bits control the source of the TOHEN signal.**Bits 3 to 0: TOHx:** These bits control the source of the TOH signal.

TOHENx	DESCRIPTION
0X00	HI-Z
0X01	TOHSOF
0X02	ROHSOF
0X03	Not used
0X04	Not used
0X05	Not used
0X06	Logic 0
0X07	Logic 1
0X08-0XFF	HI-Z

TOHx	DESCRIPTION
0X00	HI-Z
0X01	ROH
0X02	Not used
0X03	Not used
0X04	Not used
0X05	Not used
0X06	Logic 0
0X07	Logic 1
0X08-0XFF	HI-Z

Register Name: **CTRL5**Register Description: **Control Register 5 Serial Data Overhead Interface**Register Offset: **0x000C**

Bit #	7	6	5	4	3	2	1	0
Name	—	—	—	—	TSER3	TSER2	TSER1	TSER0
Default	0	0	0	0	0	0	0	0

Bits 7 to 4: These bits are unused.**Bits 3 to 0: TSERx:** These bits control the source of the TSER signal.

TSERx	DESCRIPTION
0X00	HI-Z
0X01	RSER
0X02	Not Used
0X03	Not Used
0X04	Not Used
0X05	Not Used
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

Register Name: **CTRL6**Register Description: **Control Register 6 Serial Data Overhead Interface**Register Offset: **0x000D**

Bit #	7	6	5	4	3	2	1	0
Name	TSOFI3	TSOFI2	TSOFI1	TSOFI0	TCLKI3	TCLKI2	TCLKI1	TCLKI0
Default	0	0	0	0	0	0	0	0

Bits 7 to 4: TSOFIx: These bits control the source of the TSOFI signal.**Bits 3 to 0: TCLKIx:** These bits control the source of the TCLKI signal.

TSOFIx	DESCRIPTION
0X00	HI-Z
0X01	TSOFO
0X02	RSOFO
0X03	Not Used
0X04	Not Used
0X05	Not Used
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

TCLKIx	DESCRIPTION
0X00	HI-Z
0X01	TCLKO
0X02	RCLKO
0X03	Not Used
0X04	Not Used
0X05	Not Used
0X06	Logic 0
0X07	Logic 1
0X08–0XFF	HI-Z

DS3170 INFORMATION

For more information about the DS3170, refer to the DS3170 data sheet available on our website at www.maxim-ic.com/DS3170. Software downloads are also available for this design kit.

DS3170DK INFORMATION

For more information about the DS3170DK including software downloads, consult the DS3170DK data sheet available on our website at www.maxim-ic.com/DS3170DK.

TECHNICAL SUPPORT

For additional technical support, e-mail your questions to telecom.support@dalsemi.com.

SCHEMATICS

The DS3170DK schematics are featured in the following 23 pages.

DS3170 DESIGN KIT

CREATED BY
DALLAS SEMICONDUCTOR
JUNE 26, 2004

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Page 2. DS3170 BGA
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Page 4. TCLK/RCLK/TELECOM DATA
Page 5. DS3170 RESET / GPIO
Page 6. MISC TELECOM SIGNALS
Page 7. REF OSC
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Page 11. MICROCONTROLLER BLOCK1
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Page 14. MISC USER INPUTS
Page 15. GP FPGA CONTROL / FLASH
Page 16. GP FPGA BLOCK1
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Page 18. ADDRESS/DATA HEADERS
Page 19. MICROCONTROLLER SRAM
Page 20. POWER CONN
Page 21. NOTES

Fri Mar 18 13:45:59 2005

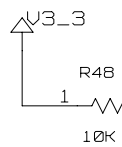
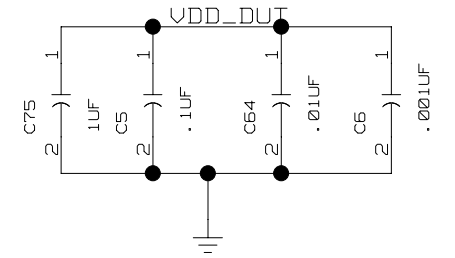
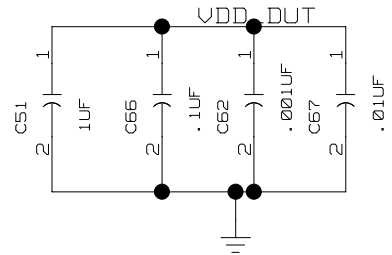
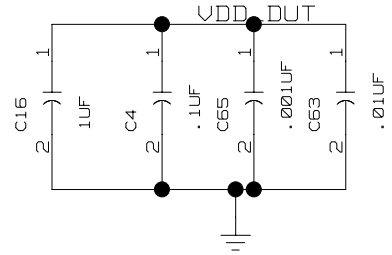
TITLE: Page 1. COVER PAGE	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 1

DS3170
100 PIN BGA

LA0	K5	A<0>/BSWAP
LA1	J2	A<1>
LA2	K2	A<2>
LA3	H3	A<3>
LA4	J3	A<4>
LA5	K3	A<5>
LA6	H4	A<6>
LA7	J4	A<7>
LA8	H5	A<8>
XD0	J5	D<0>/SPI_MISO
XD1	K9	D<1>/SPI_MOSI
XD2	J6	D<2>/SPI_SCLK
XD3	H6	D<3>
XD4	K7	D<4>
XD5	J7	D<5>/SPI_SWAP
XD6	H7	D<6>/SPI_CPHA
XD7	K8	D<7>/SPI_CPOL
XD8	J8	D<8>
XD9	G6	D<9>
XD10	J9	D<10>
XD11	J10	D<11>
XD12	H8	D<12>
XD13	H9	D<13>
XD14	H10	D<14>
XD15	G8	D<15>

RDY*	J1	RDY_70
INT*	D8	INT_70
MODE	F3	MODE
WIDTH	H2	WIDTH_70
SPI	C3	SPI
VSS1	C1	
VSS2	K1	
VSS3	K6	
VSS4	G10	
VSS5	A10	
VSS6	A2	
AVSSR	B5	
AVSST	E4	
AVSSJ	D2	
AVSSC	G1	
GPIO<1>	E8	GPIO_1
GPIO<2>	E7	GPIO_2
GPIO<3>	F7	GPIO_3
GPIO<4>	G7	GPIO_4
GPIO<5>	F6	GPIO_5
GPIO<6>	G5	GPIO_6
GPIO<7>	D3	GPIO_7
GPIO<8>	D4	GPIO_8
TEST*	F5	TEST_70
HIZ*	B4	HIZ_70
RST*	E6	RST_70_OUT

I1
NA1
DS3170
U7
DS3170_BGA_U



TLCLK	B7	TLCLK70
TPOS/TDAT	E9	TPOS_70
TNEG	D9	TNEG_70
TXP1	E1	TXP_70
TXP2	E2	
TXN1	F1	TXN_70
TXN2	F2	
RLCLK	A8	RLCLK70
RPOS/RDAT	F10	RPOS_70
RNEG/RLCV	F9	RNEG_70
RXP	A4	RXP_70
RXN	A3	RXN_70
TOH	C7	TOH70
TOHEN	E10	TOHEN70
TOHCLK	D7	TOHCLK70
TOHSOF	G9	TOHSOF70
ROH	B6	ROH70
ROHCLK	C9	ROHCLK70
ROHSOF	F8	ROHSOF70
TCLKI	C10	TCLKI70
TSOFI	A9	TSOFI70
TSER	B10	TSER70
TCLKO/TGCLK	B9	TCLKO70
TSOFO/TIDEN	C8	TSOFO70
RSER	C6	RSER70
RCLKO/RGCLK	A6	RCLKO70
RSOFO/RDEN	B8	RSOFO70

Fri Mar 18 13:46:03 2005

TITLE:	Page 2. DS3170 BGA	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	2

D

D

C

C

B

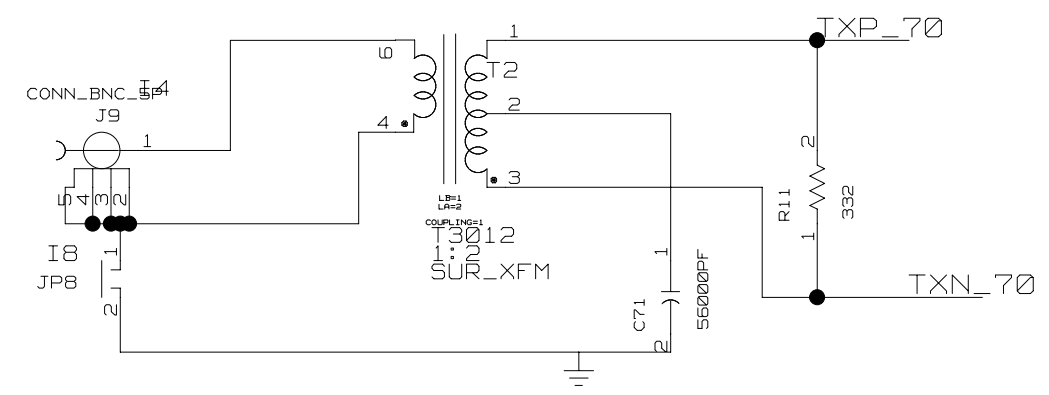
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A

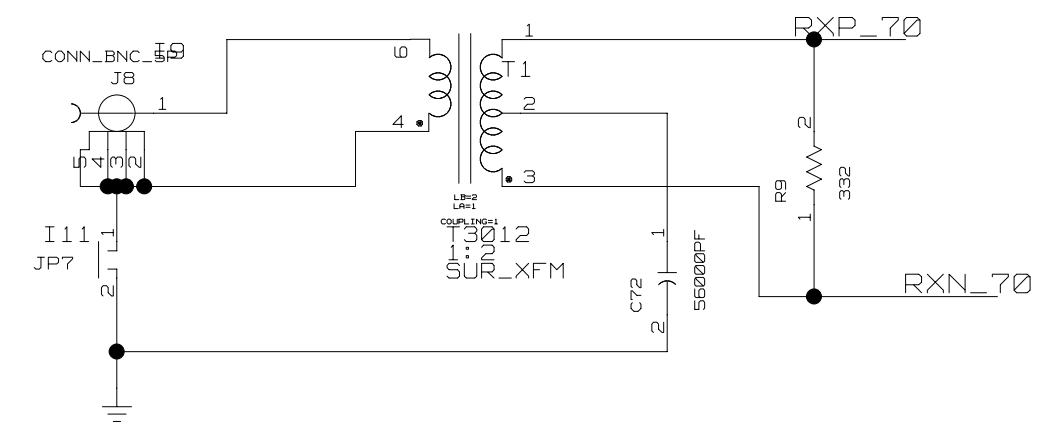
A

DS3170
100 PIN BGA
LIU INTERFACE

TRANSMIT



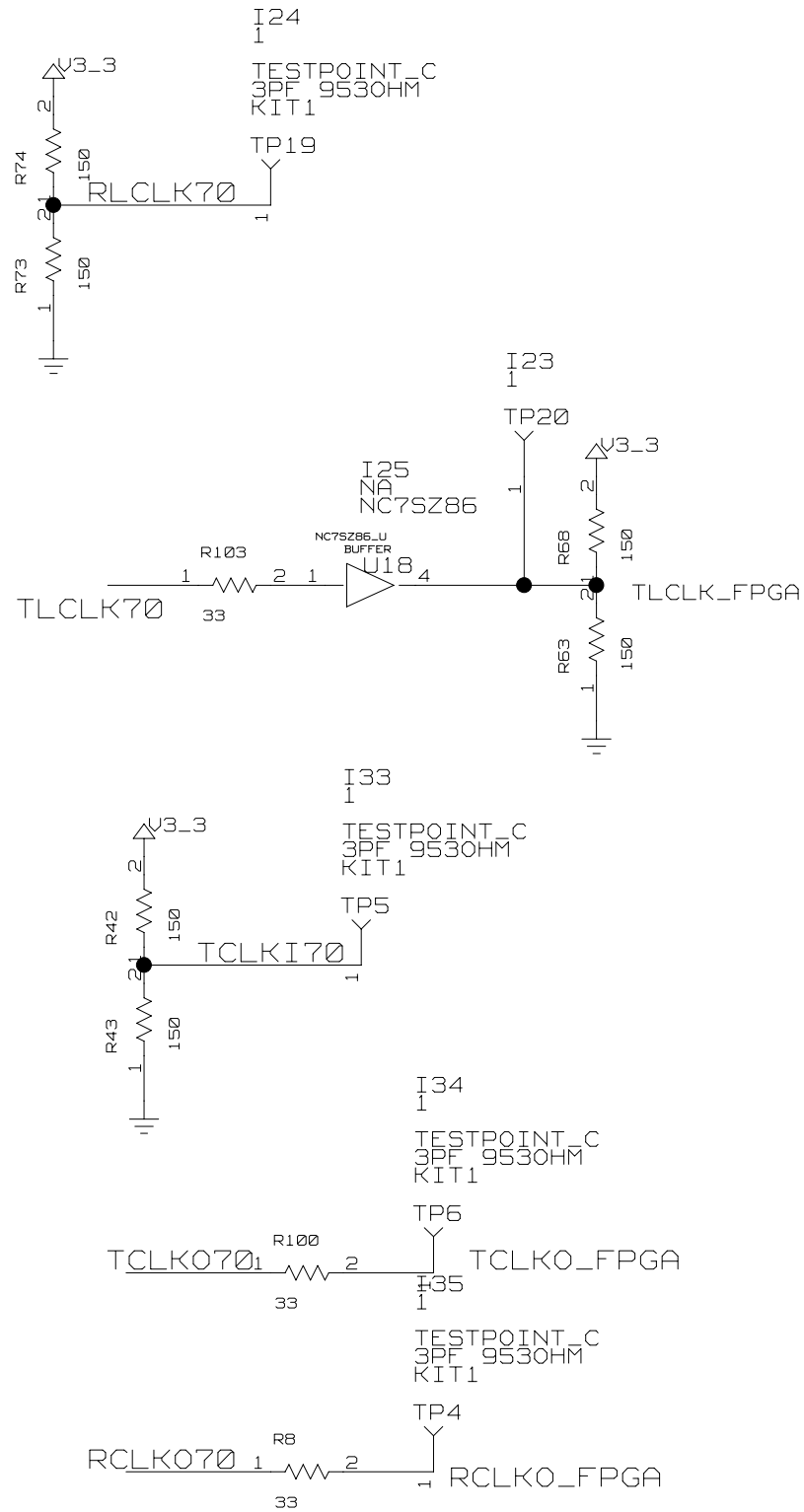
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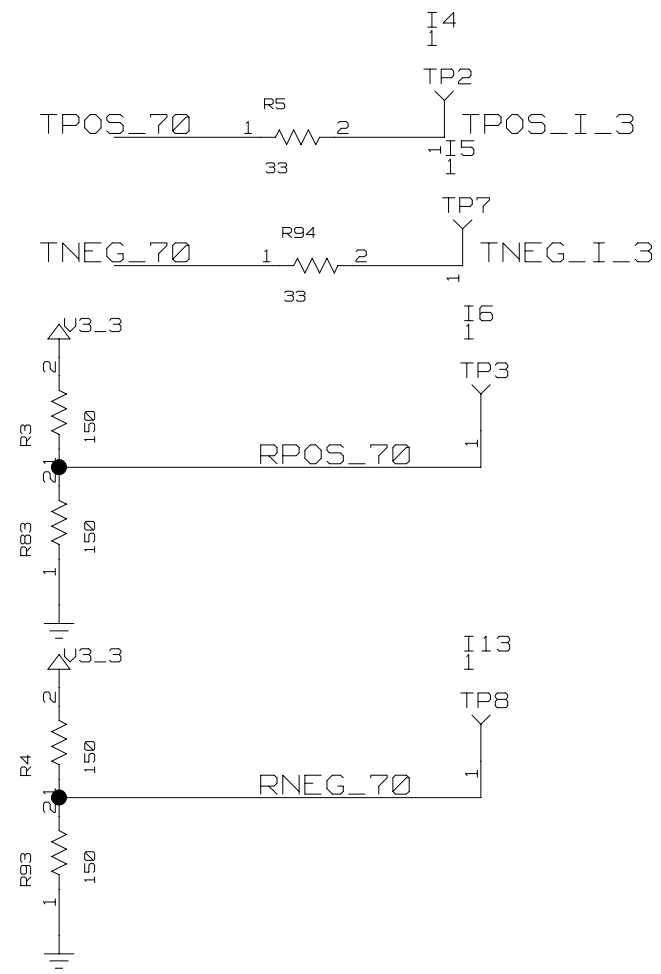
Fri Mar 18 13:46:04 2005

TITLE: Page 3. LIU INTERFACE	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 3

TCLK/RCLK TERMINATION

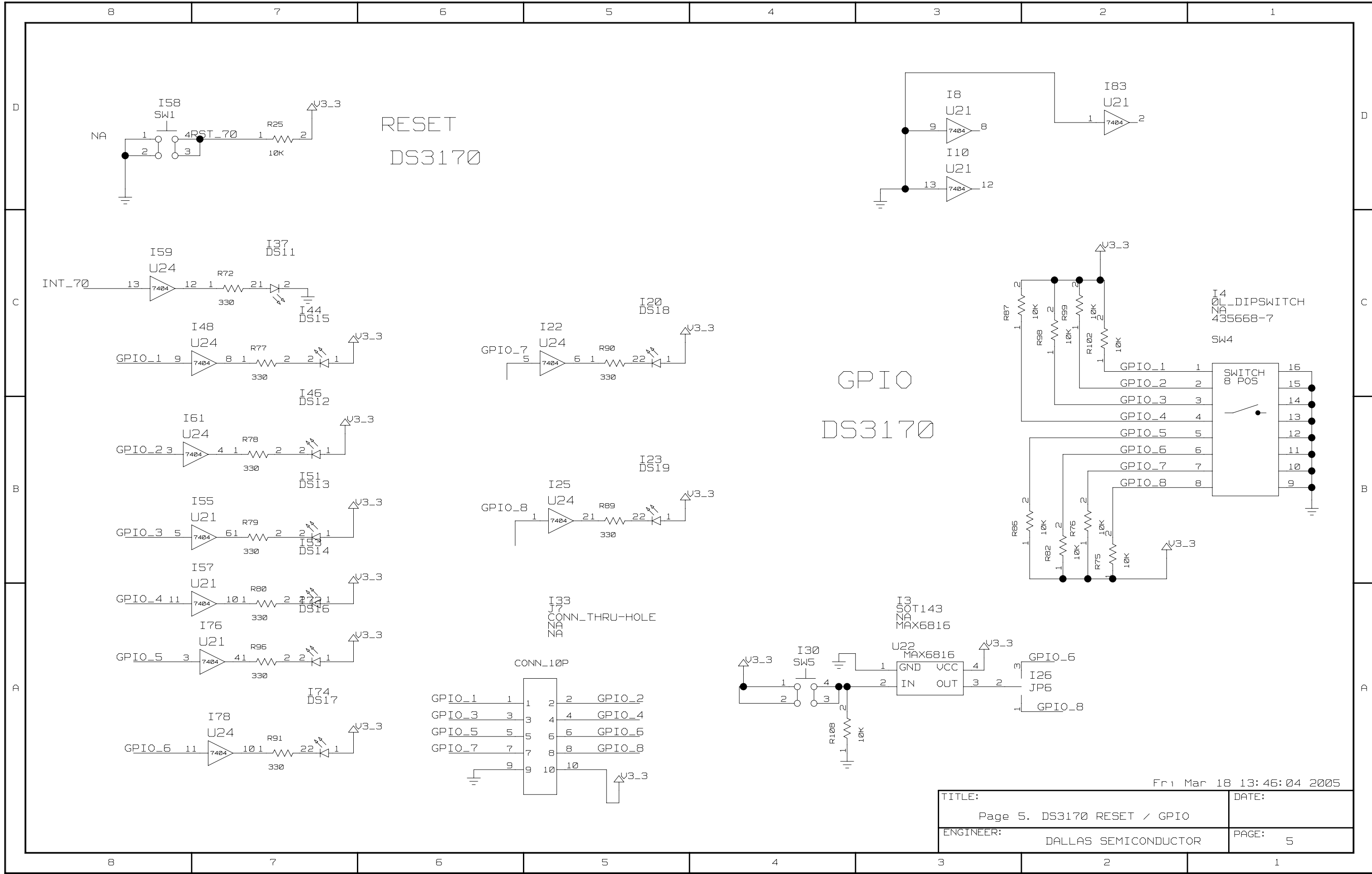


TELECOM DATA IO TPOS/TNEG/RPOS/RNEG



Fri Mar 18 13:46:04 2005

TITLE: Page 4. TCLK/RCLK/TELECOM DATA	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 4



RESET
DS3170

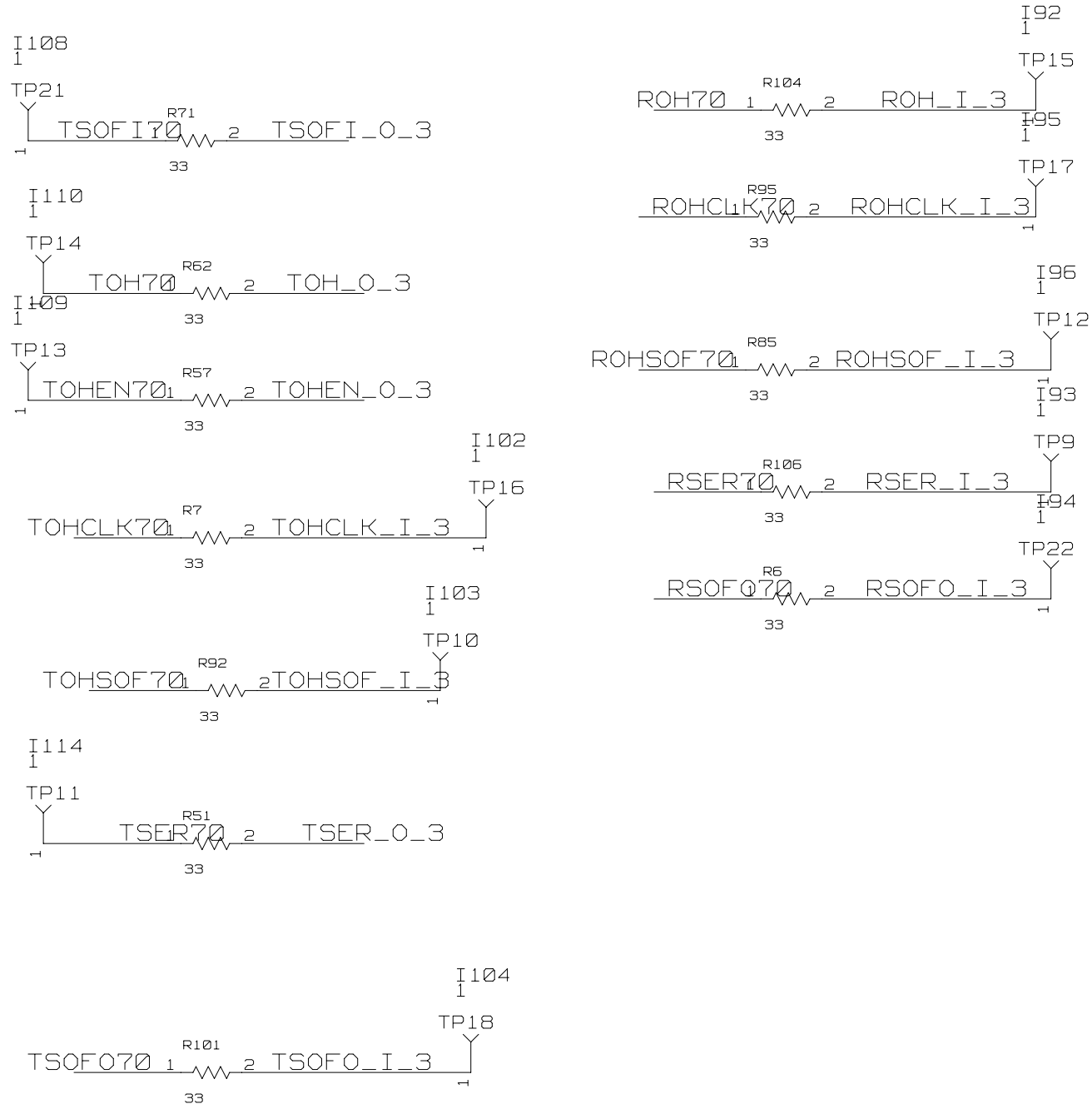
GPIO
DS3170

Fri Mar 18 13:46:04 2005

TITLE:	Page 5. DS3170 RESET / GPIO	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	5

DS3170

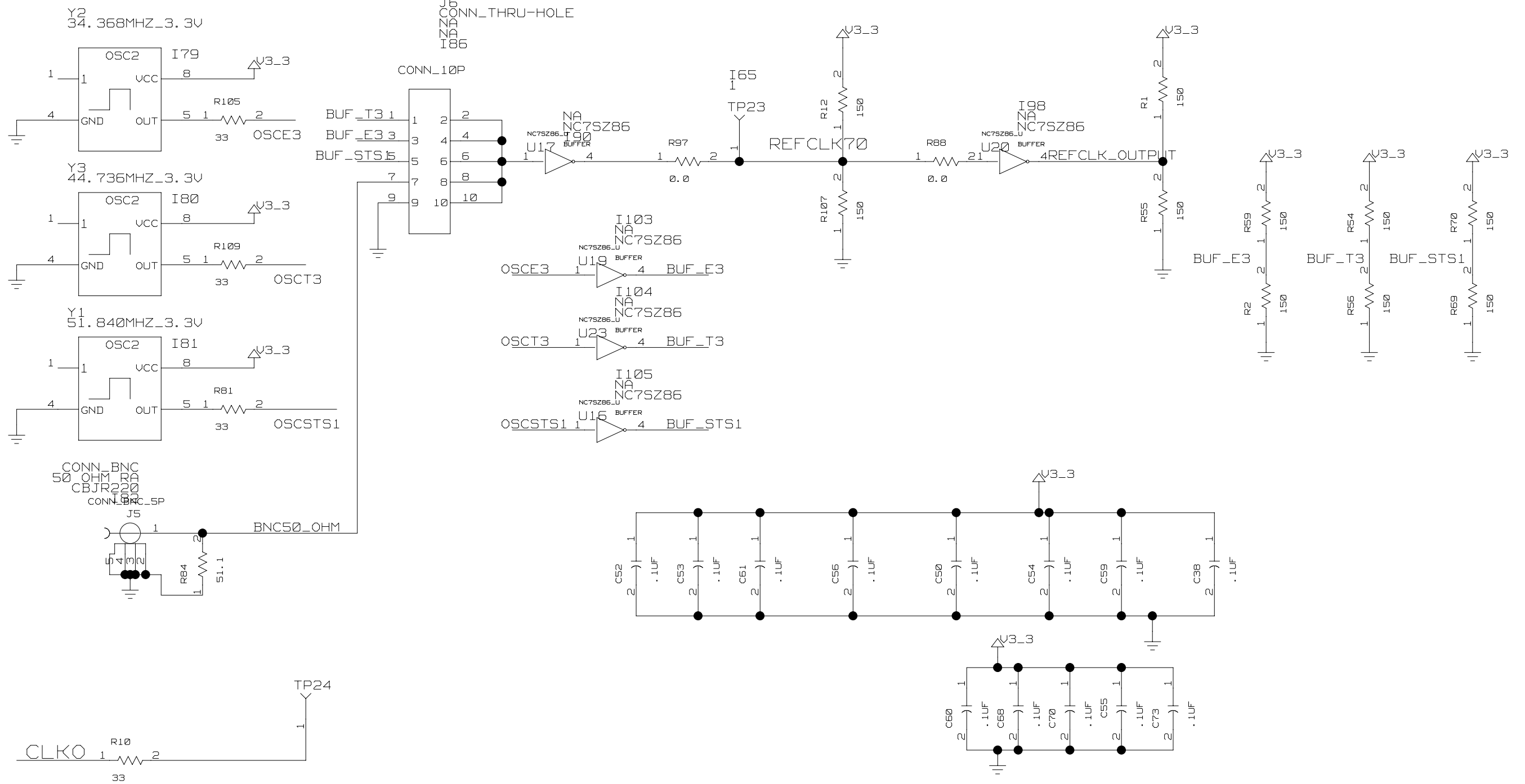
MISC TELECOM TERM



Fri Mar 18 13:46:05 2005

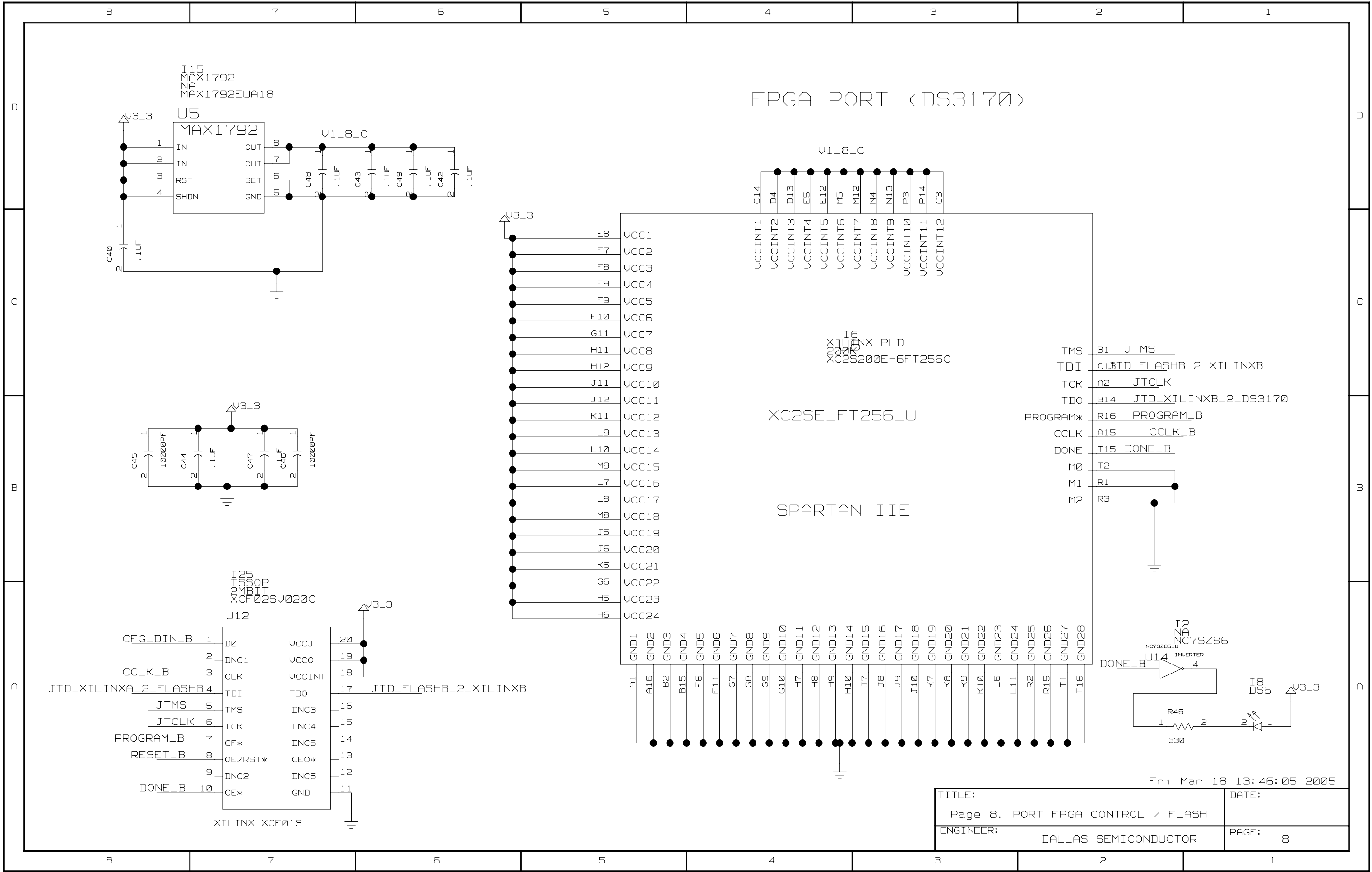
TITLE: Page 6. MISC TELECOM SIGNALS	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 6

REFERENCE CLOCK



Fri Mar 18 13:46:05 2005

TITLE:	Page 7. REF OSC	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	7



FPGA PORT (DS3170)

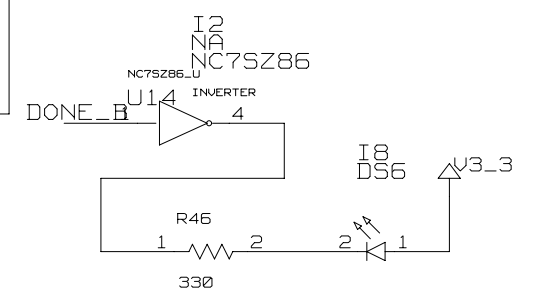
- VCCINT1
- VCCINT2
- VCCINT3
- VCCINT4
- VCCINT5
- VCCINT6
- VCCINT7
- VCCINT8
- VCCINT9
- VCCINT10
- VCCINT11
- VCCINT12

I16
XILINX_PLD
XC25200E-6FT256C

XC25E_FT256_U

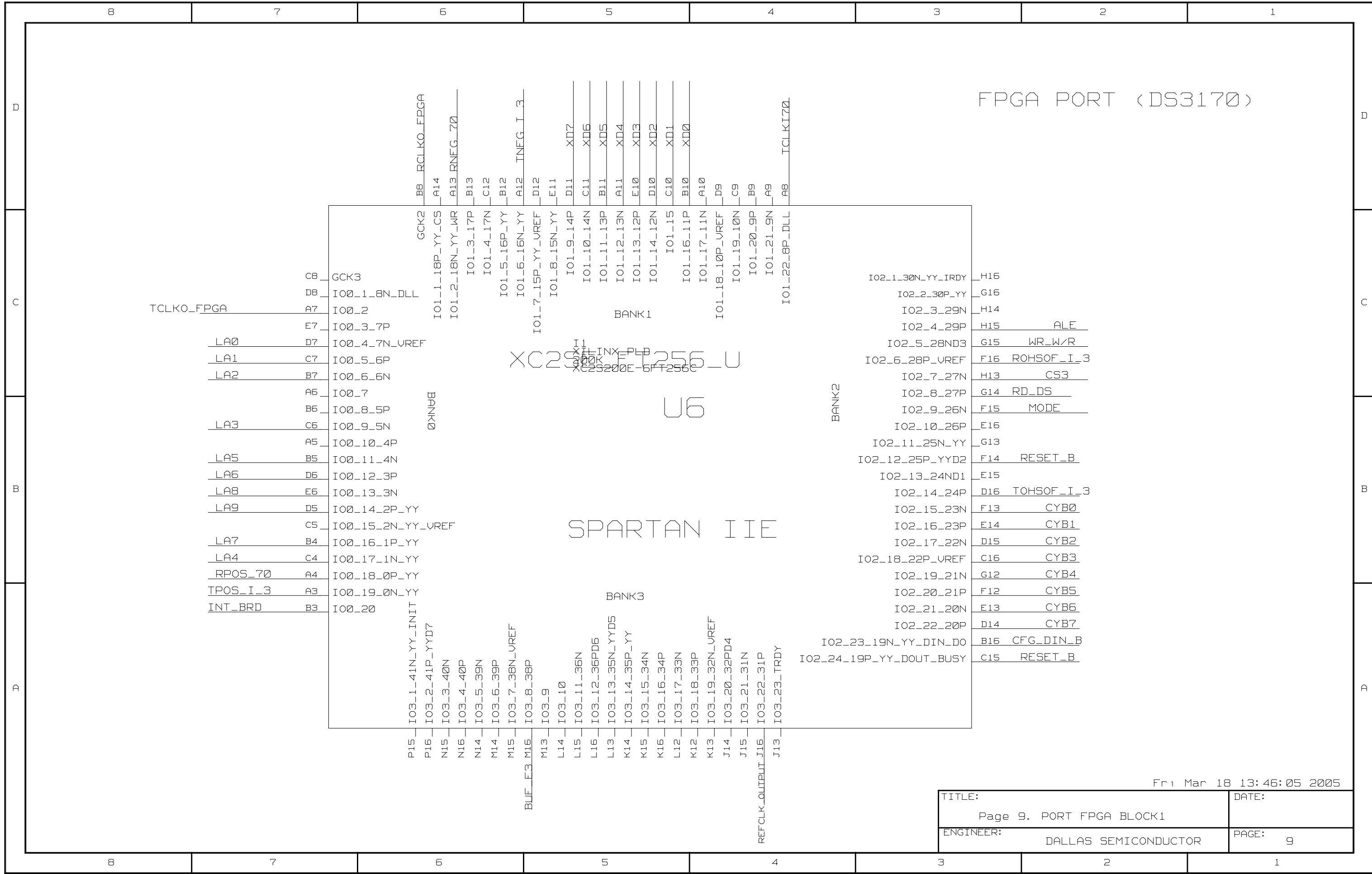
SPARTAN IIE

- TMS B1 JTMS
- TDI C1 JTD_FLASHB_2_XILINXB
- TCK A2 JTCLK
- TDO B14 JTD_XILINXB_2_DS3170
- PROGRAM* R16 PROGRAM_B
- CCLK A15 CCLK_B
- DONE T15 DONE_B
- M0 T2
- M1 R1
- M2 R3



Fri Mar 18 13:46:05 2005

TITLE: Page 8. PORT FPGA CONTROL / FLASH	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 8



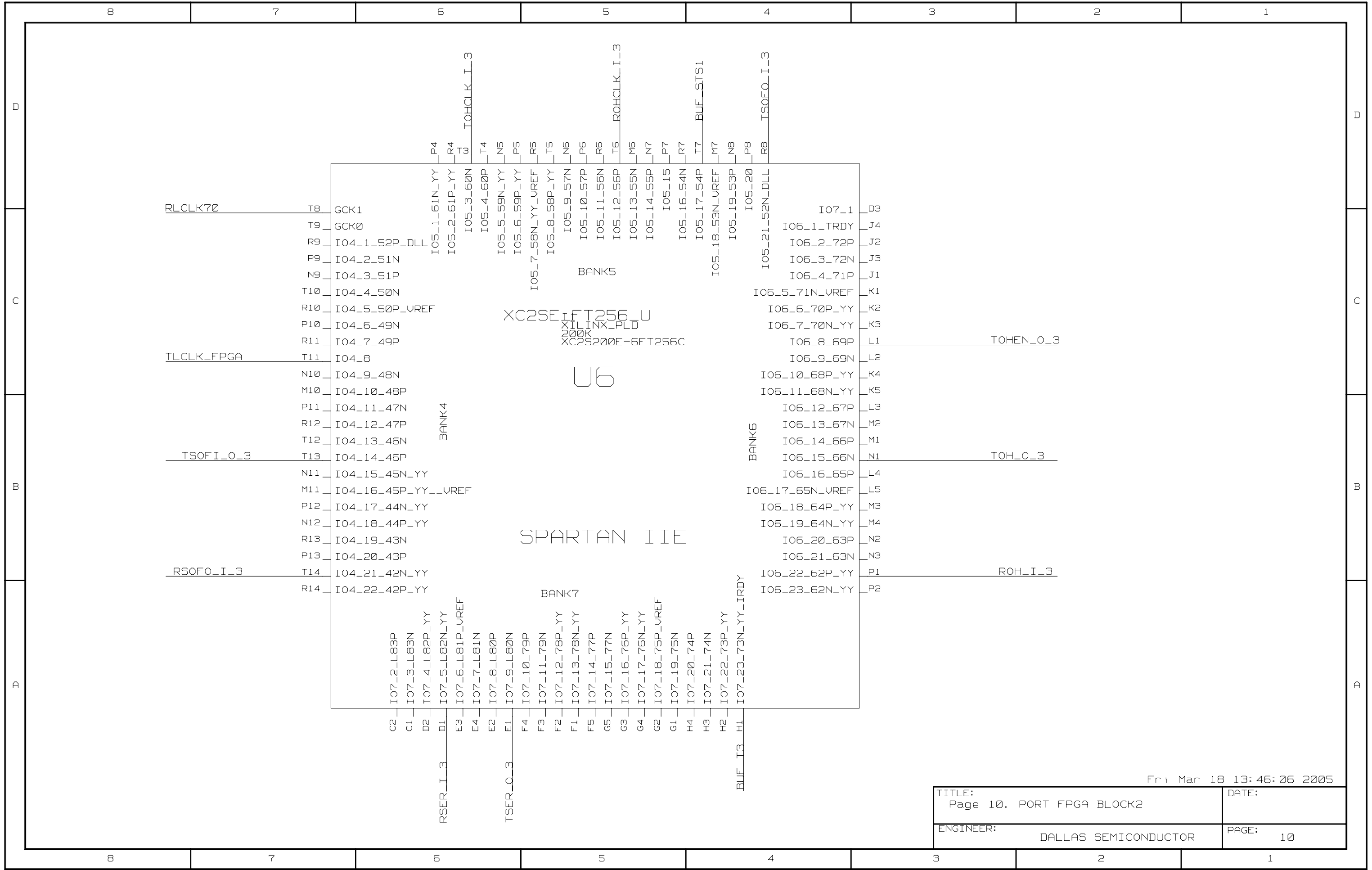
FPGA PORT (DS3170)

SPARTAN IIE

XC2S200E-6FT256C

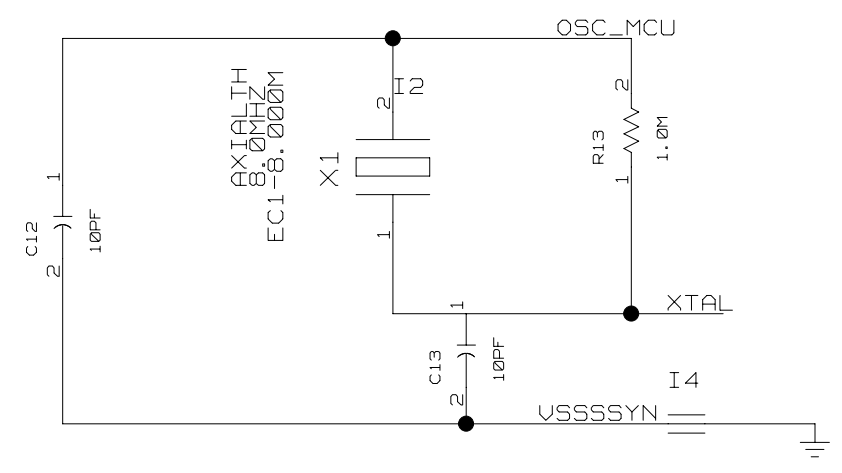
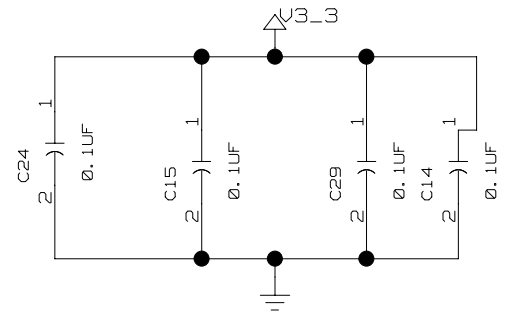
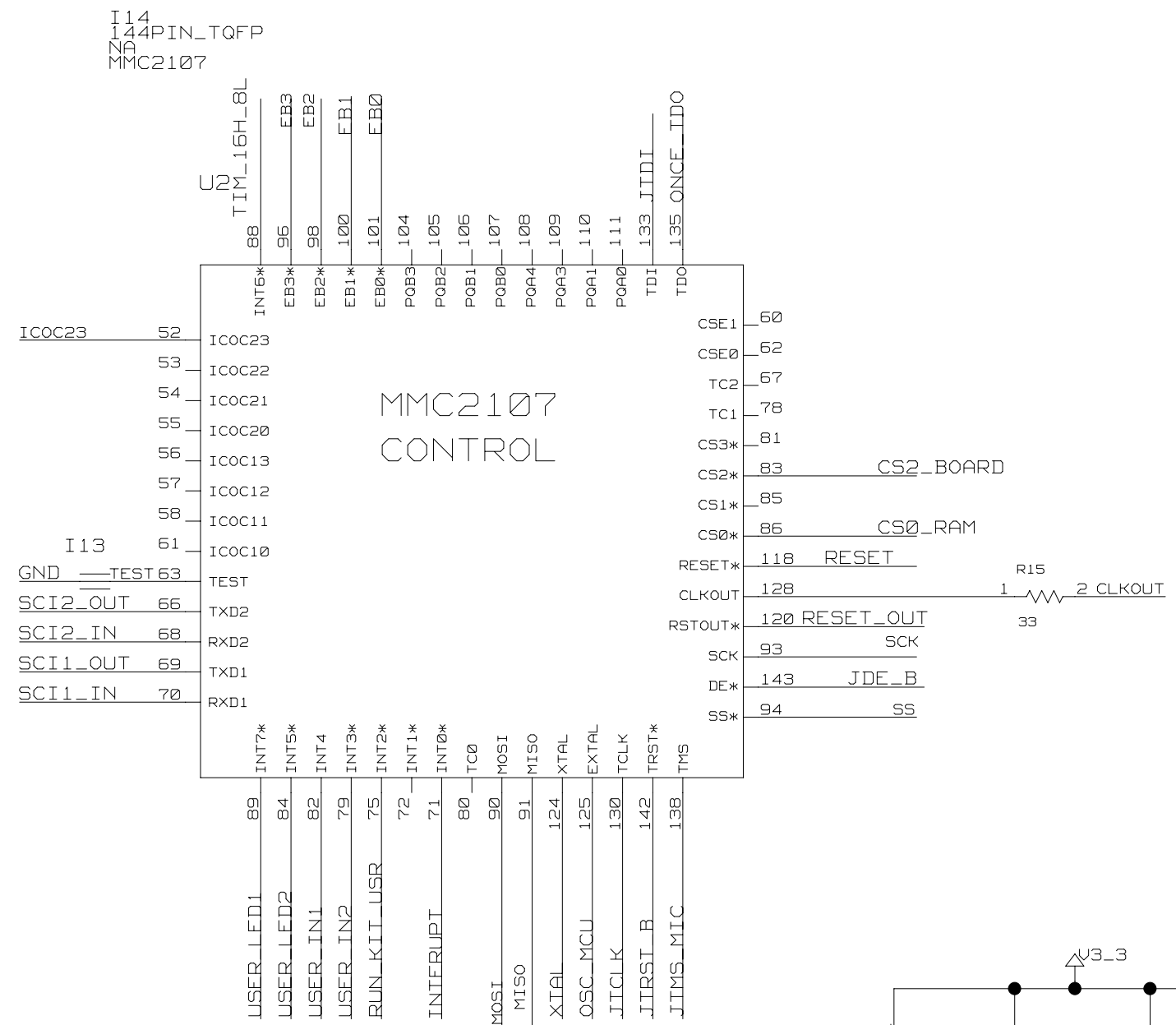
Fri Mar 18 13:46:05 2005

TITLE:	Page 9. PORT FPGA BLOCK1	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	9



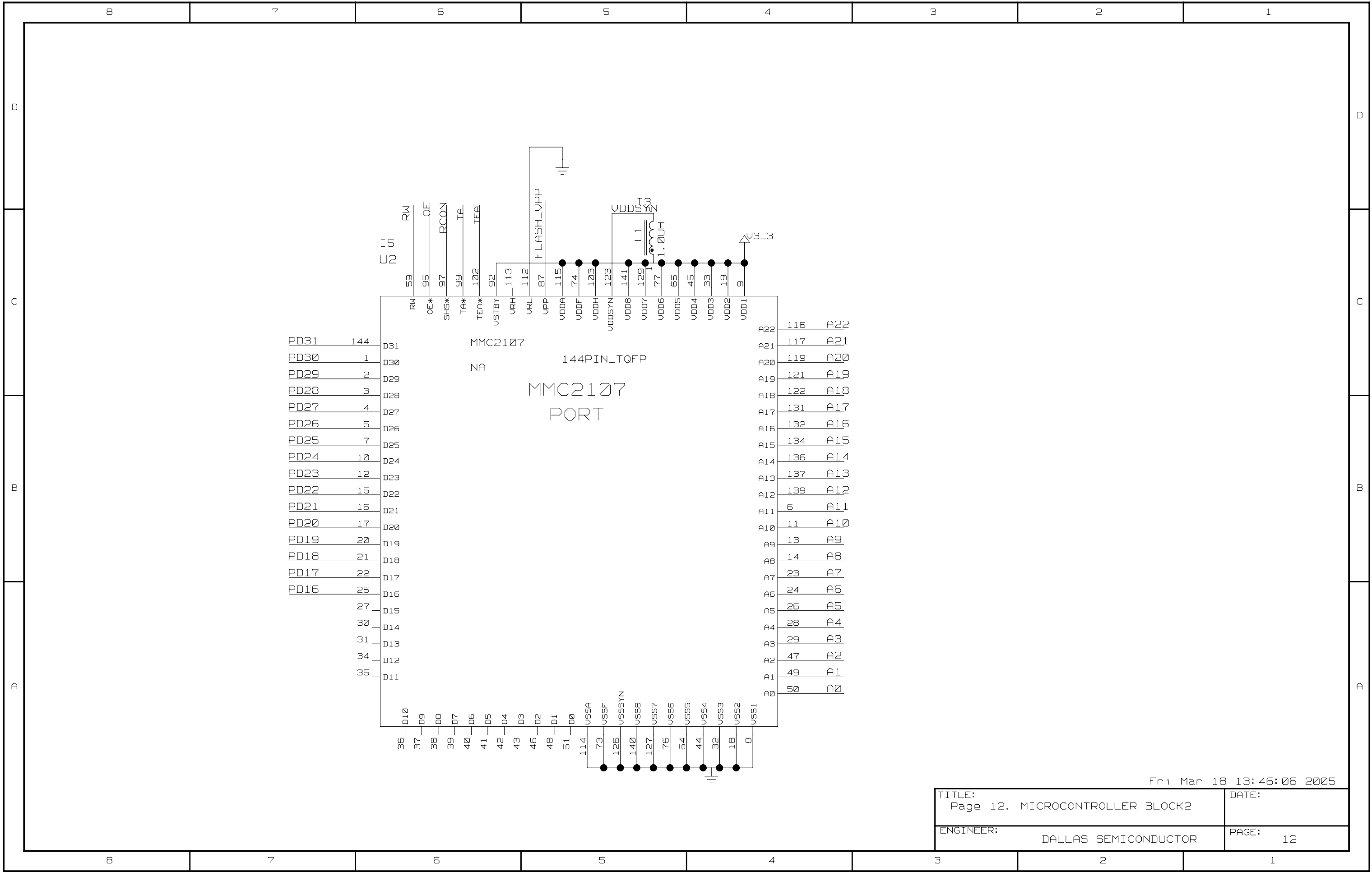
Fri Mar 18 13:46:06 2005

TITLE: Page 10. PORT FPGA BLOCK2	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 10



Fri Mar 18 13:46:06 2005

TITLE: Page 11. MICROCONTROLLER BLOCK1	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 11



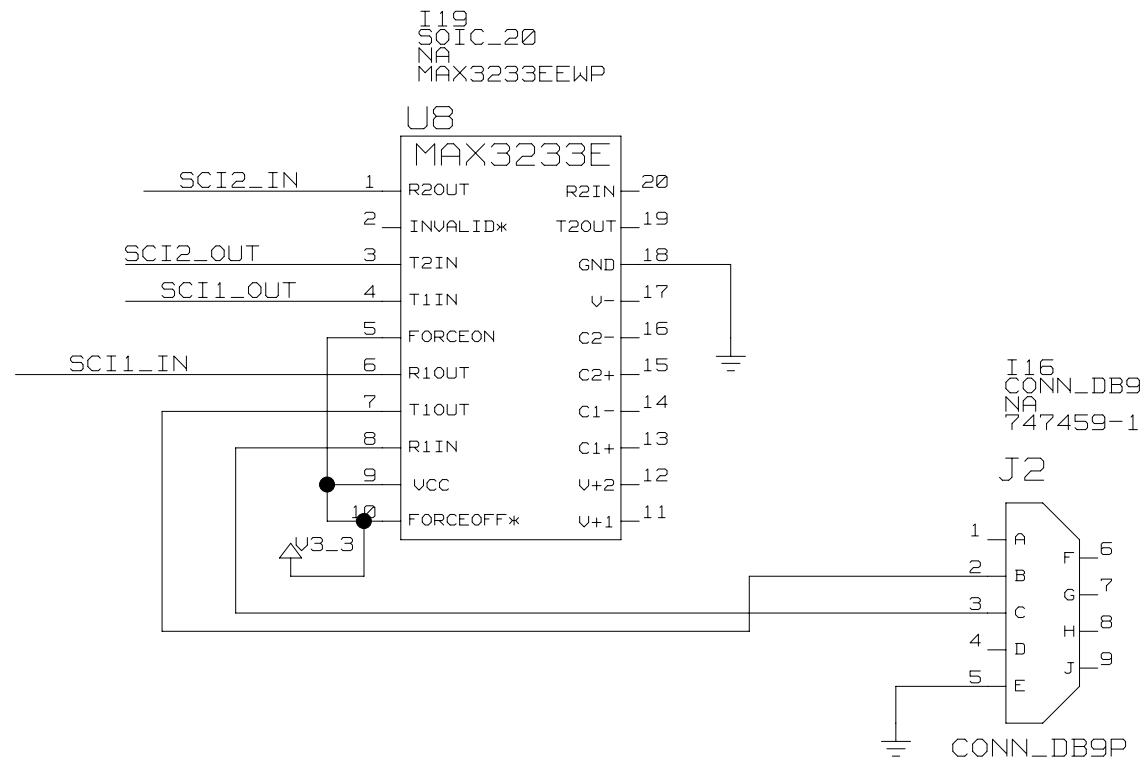
PD31	144	D31
PD30	1	D30
PD29	2	D29
PD28	3	D28
PD27	4	D27
PD26	5	D26
PD25	7	D25
PD24	10	D24
PD23	12	D23
PD22	15	D22
PD21	16	D21
PD20	17	D20
PD19	20	D19
PD18	21	D18
PD17	22	D17
PD16	25	D16
	27	D15
	30	D14
	31	D13
	34	D12
	35	D11

A22	116	A22
A21	117	A21
A20	119	A20
A19	121	A19
A18	122	A18
A17	131	A17
A16	132	A16
A15	134	A15
A14	136	A14
A13	137	A13
A12	139	A12
A11	6	A11
A10	11	A10
A9	13	A9
A8	14	A8
A7	23	A7
A6	24	A6
A5	26	A5
A4	28	A4
A3	29	A3
A2	47	A2
A1	49	A1
A0	50	A0

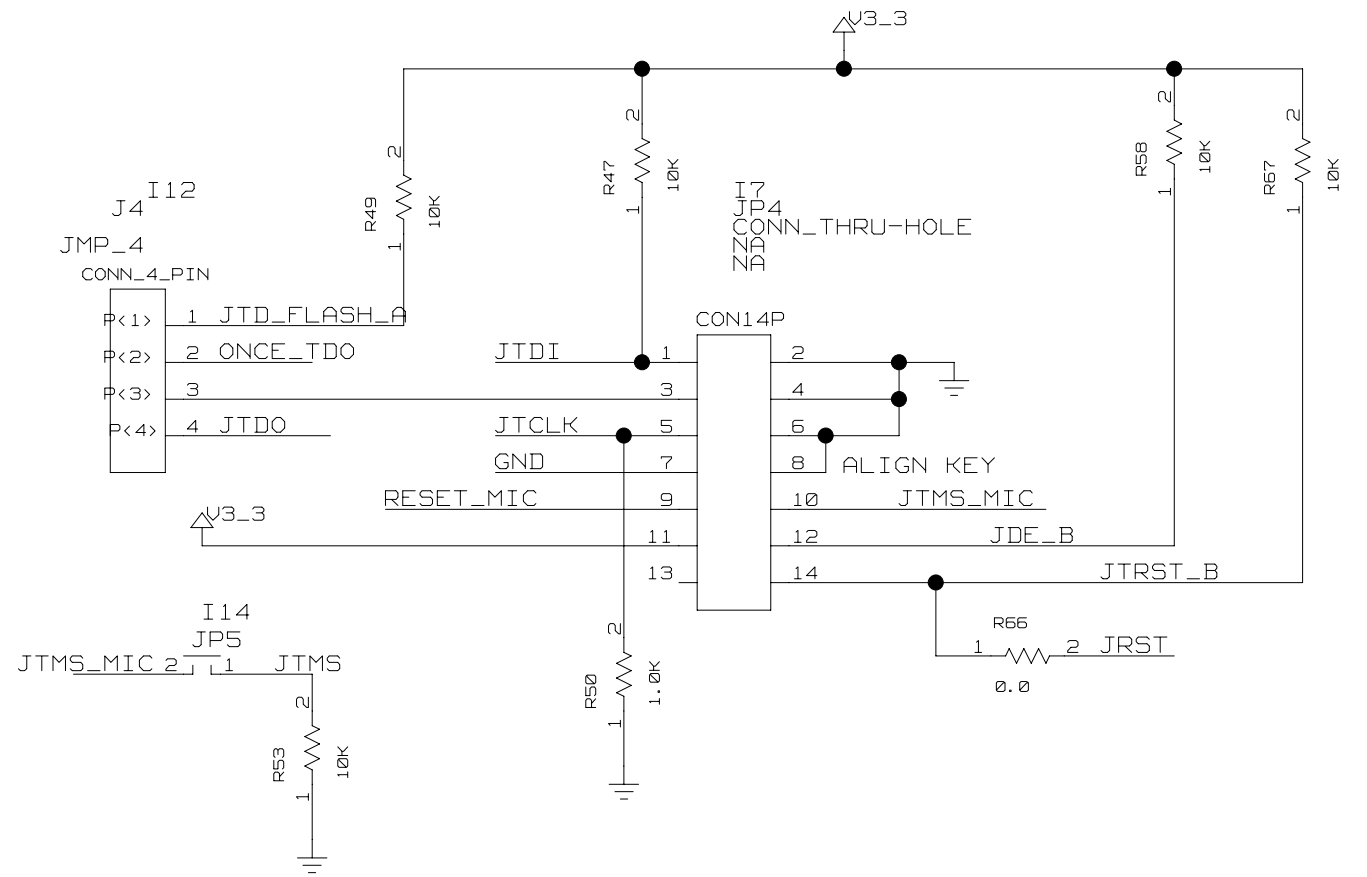
Fri Mar 18 13:46:06 2005

TITLE: Page 12. MICROCONTROLLER BLOCK2	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 12

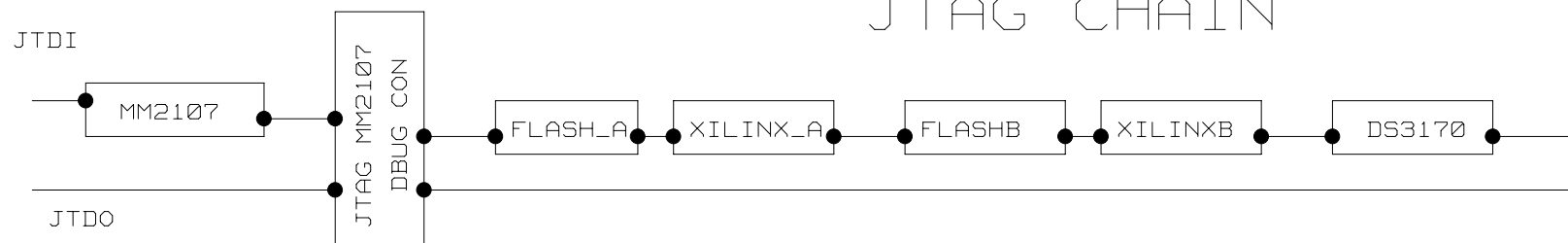
SERIAL INTERFACE



JTAG CON



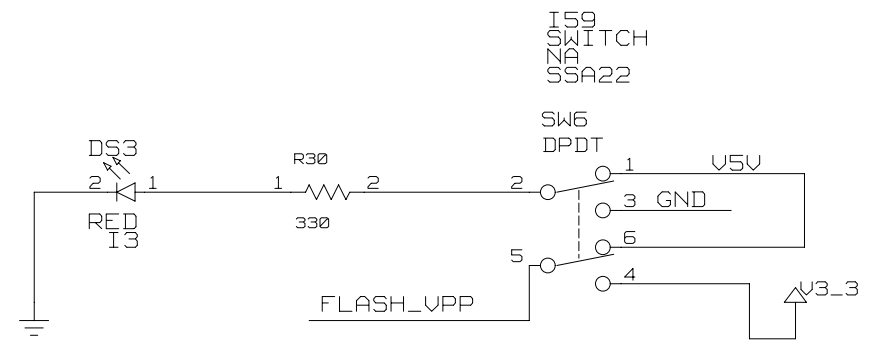
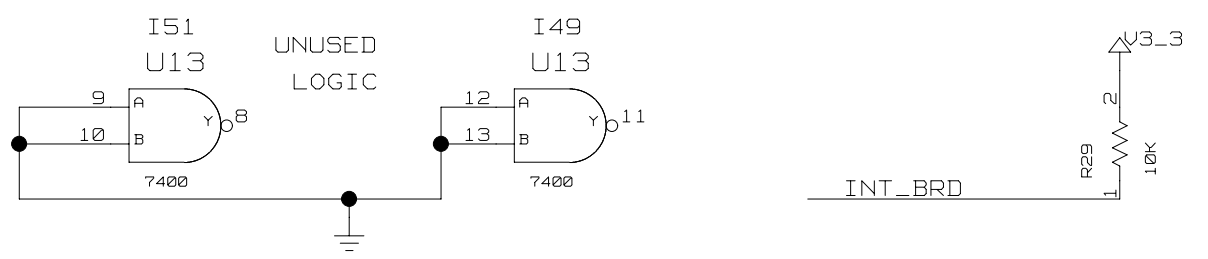
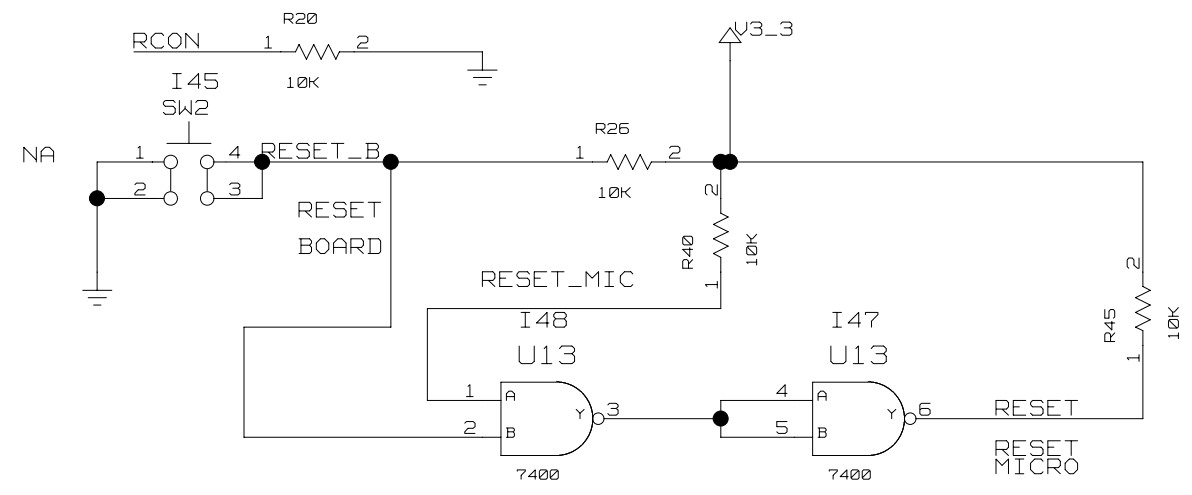
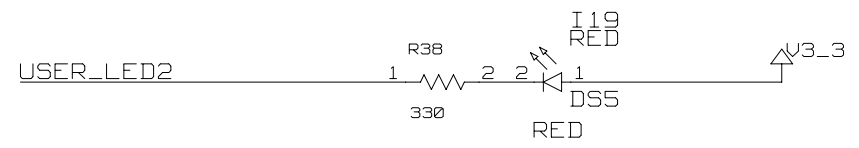
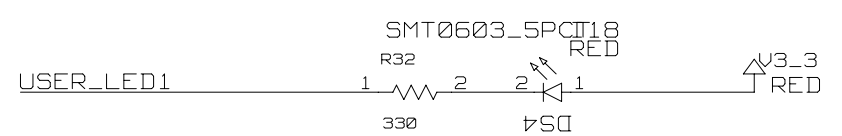
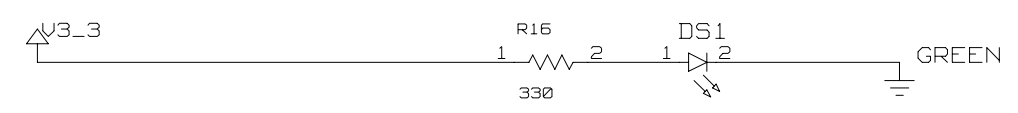
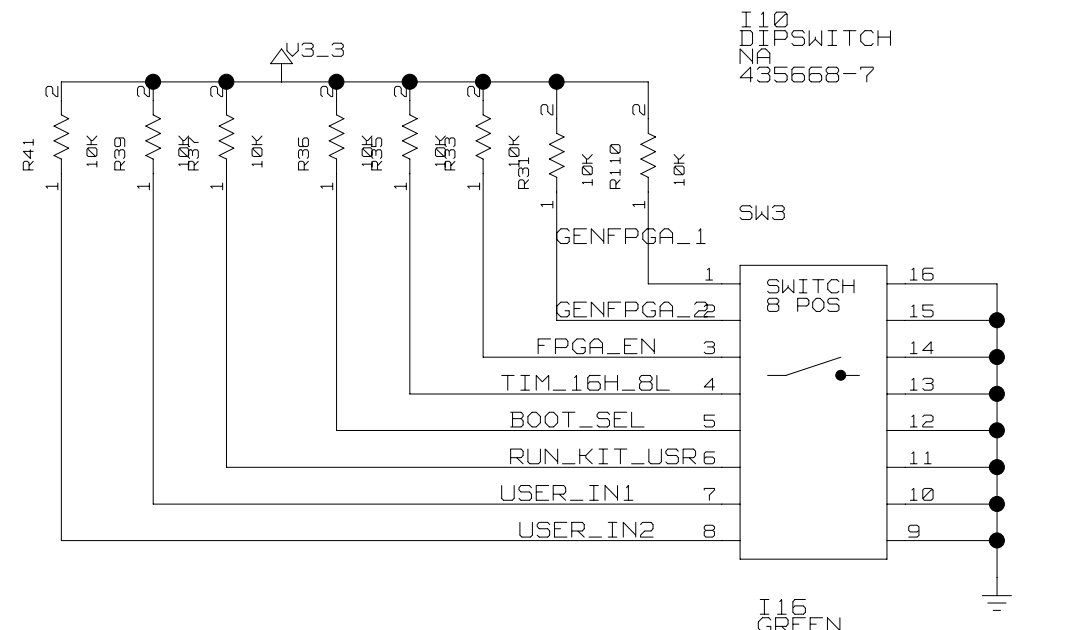
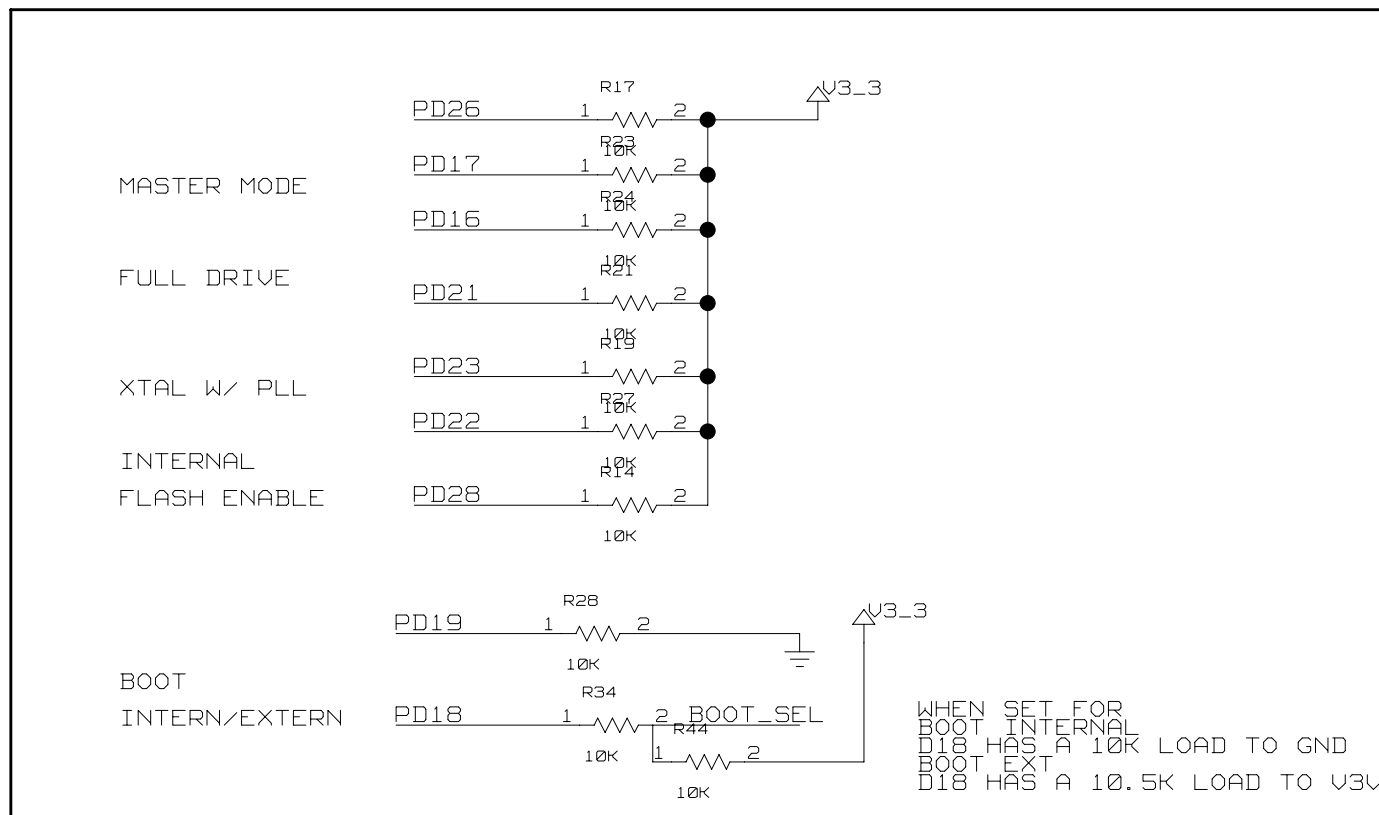
JTAG CHAIN



Fri Mar 18 13:46:06 2005

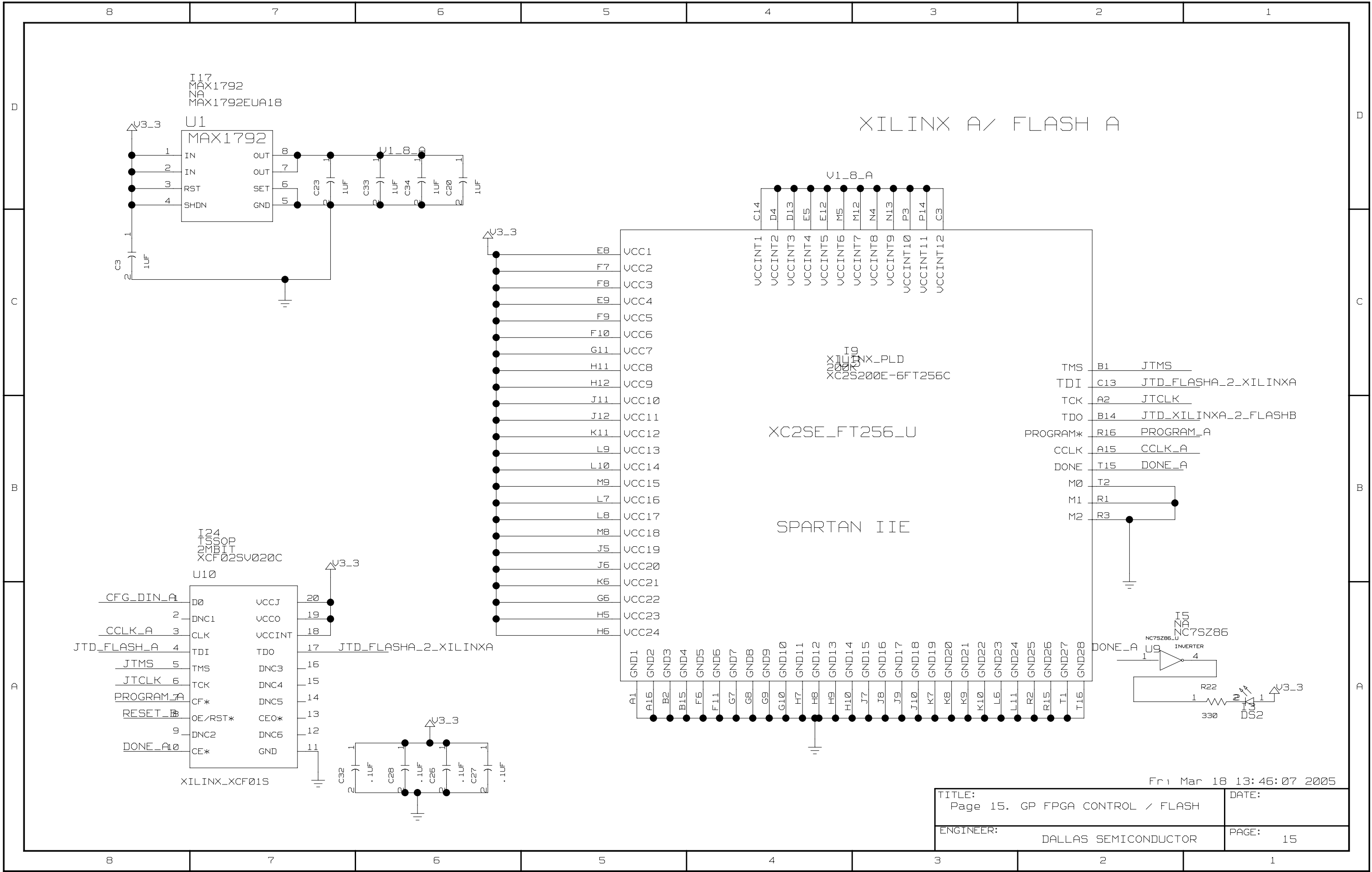
TITLE: Page 13. SERIAL/JTAG CONN	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 13

RESET CONFIGURATION



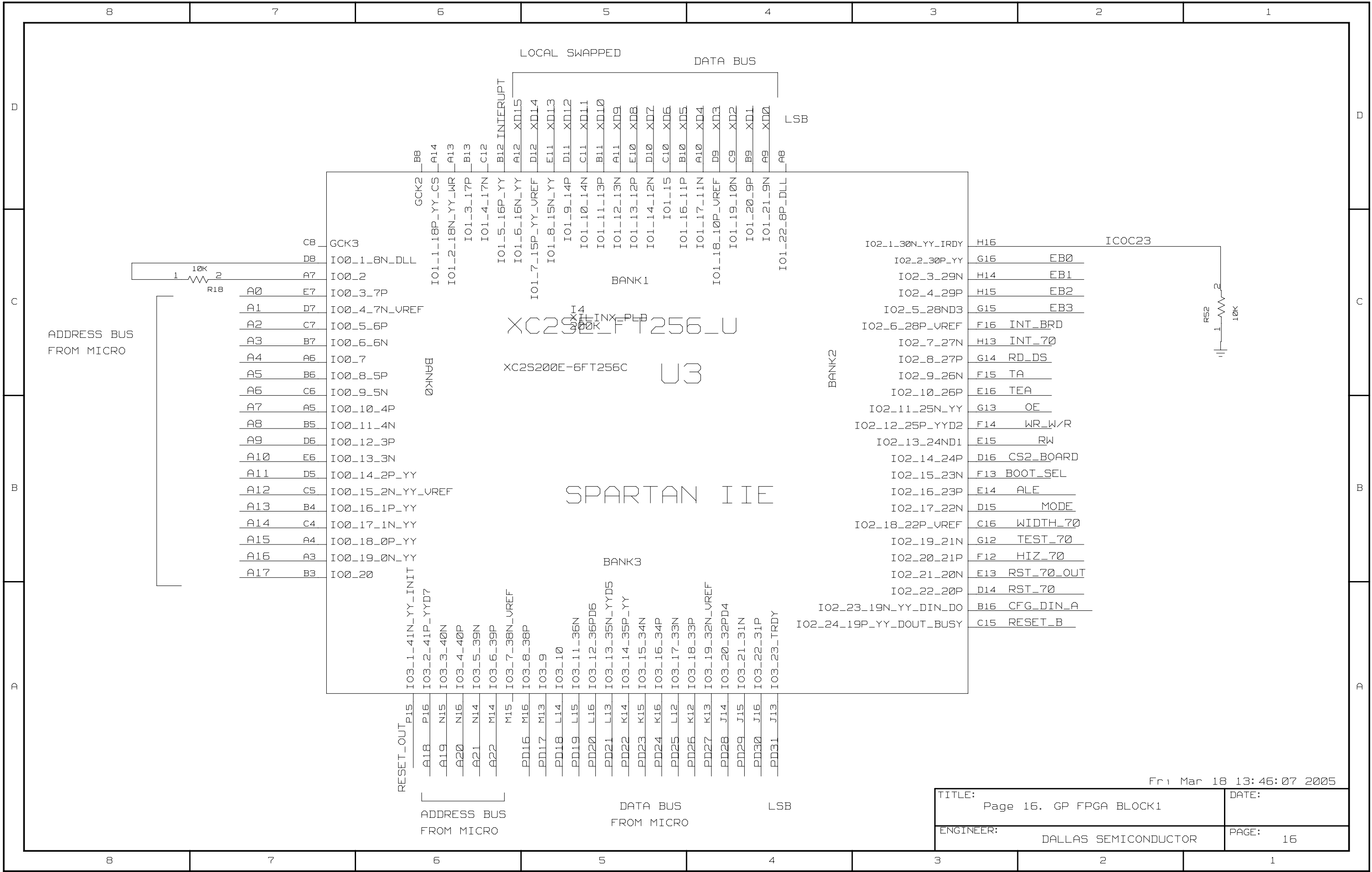
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TITLE: Page 14. MISC USER INPUTS	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 14



Fri Mar 18 13:46:07 2005

TITLE: Page 15. GP FPGA CONTROL / FLASH	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 15



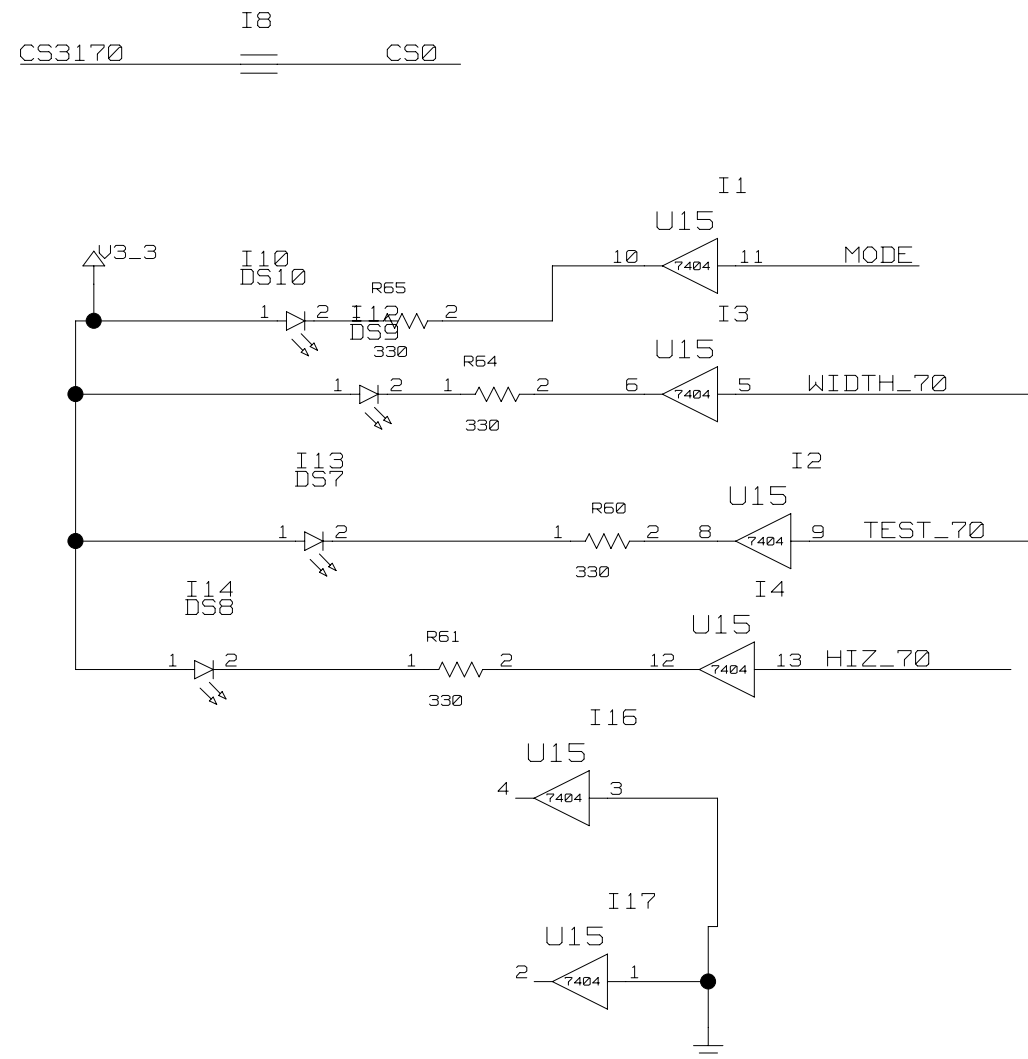
Fri Mar 18 13:46:07 2005

TITLE: Page 16. GP FPGA BLOCK1	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 16

I18
 J3
 0L_THROUGH HOLE
 NA
 TSW-125-07-T-D

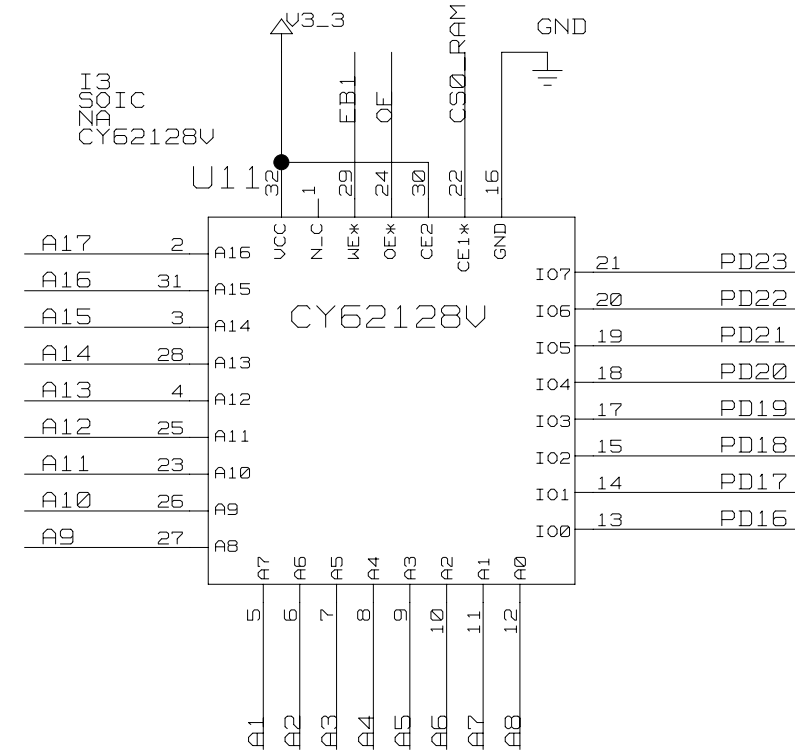
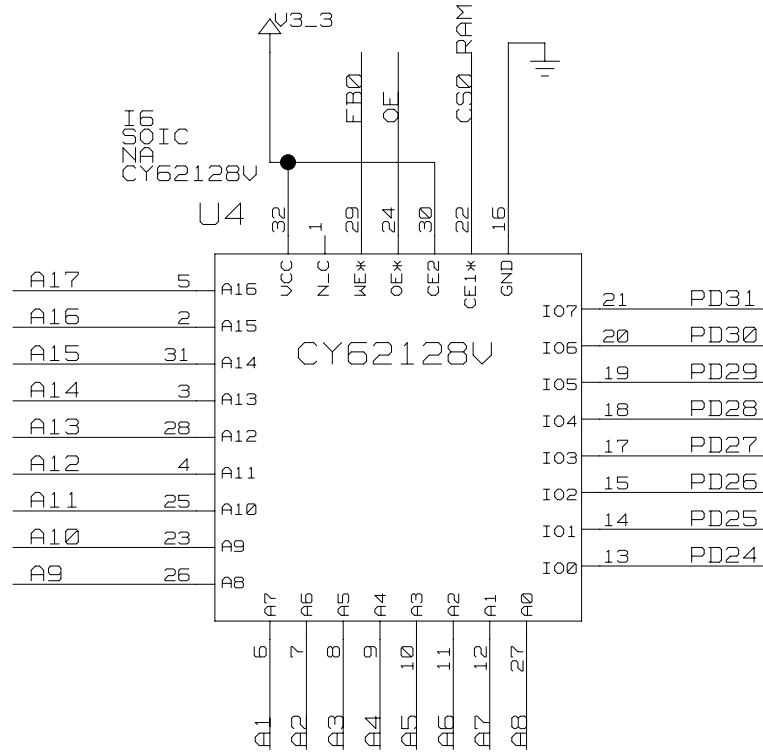
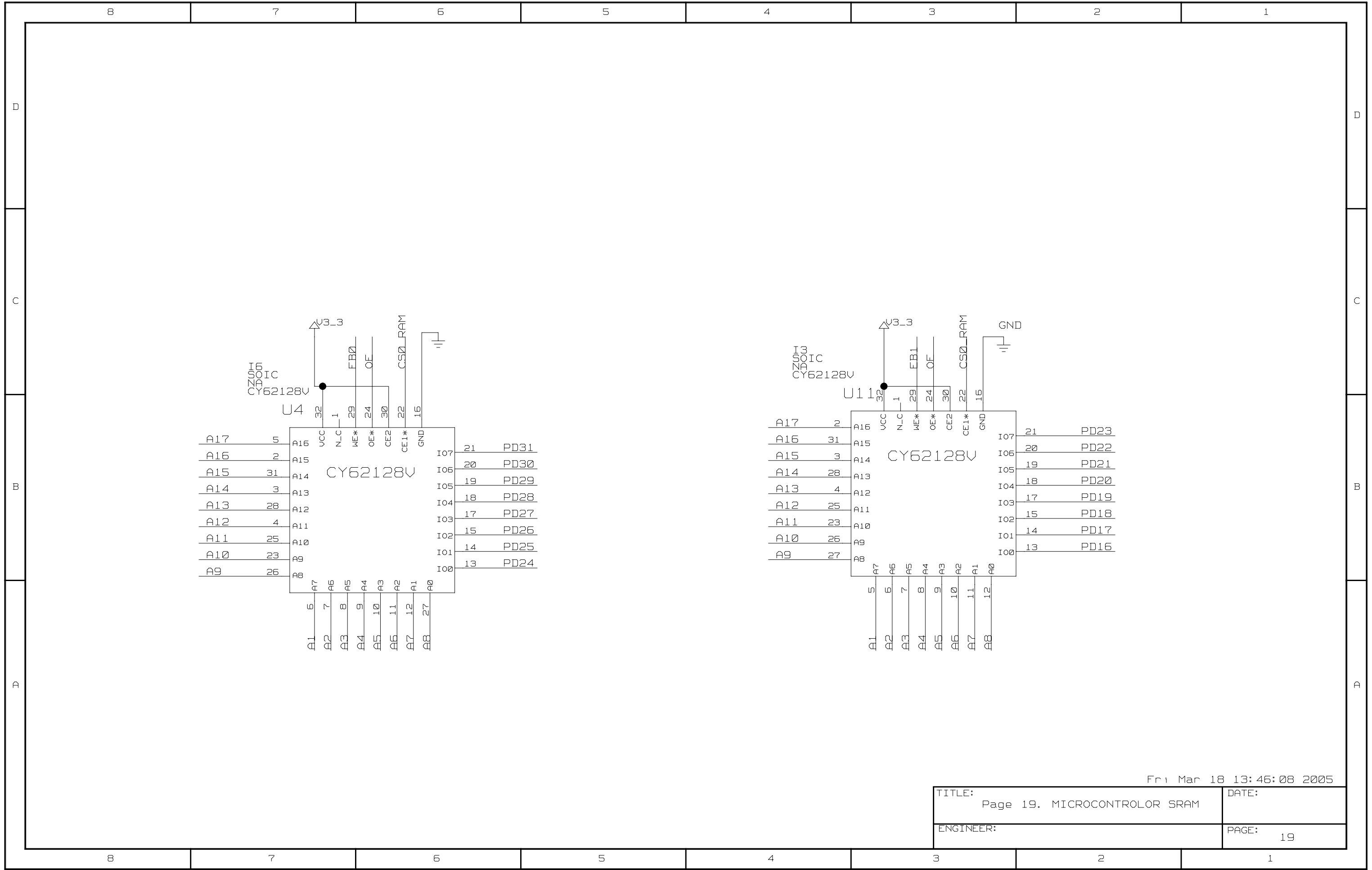
LA0	1	1	2	2	XD0
LA1	3	3	4	4	XD1
LA2	5	5	6	6	XD2
LA3	7	7	8	8	XD3
LA4	9	9	10	10	XD4
LA5	11	11	12	12	XD5
LA6	13	13	14	14	XD6
LA7	15	15	16	16	XD7
LA8	17	17	18	18	XD8
LA9	19	19	20	20	XD9
CS3170	21	21	22	22	XD10
CS3	23	23	24	24	XD11
INT_70	25	25	26	26	XD12
RST_70_OUT	27	27	28	28	XD13
RDY_70	29	29	30	30	XD14
CYB0	31	31	32	32	XD15
CYB1	33	33	34	34	SPI
CYB2	35	35	36	36	ALE
CYB3	37	37	38	38	RD_DS
CYB4	39	39	40	40	WR_W/R
CYB5	41	41	42	42	CS_OUT
CYB6	43	43	44	44	MODE
CYB7	45	45	46	46	WIDTH_70
GND	47	47	48	48	TEST_70
GND	49	49	50	50	HIZ_70

MISC HEADERS



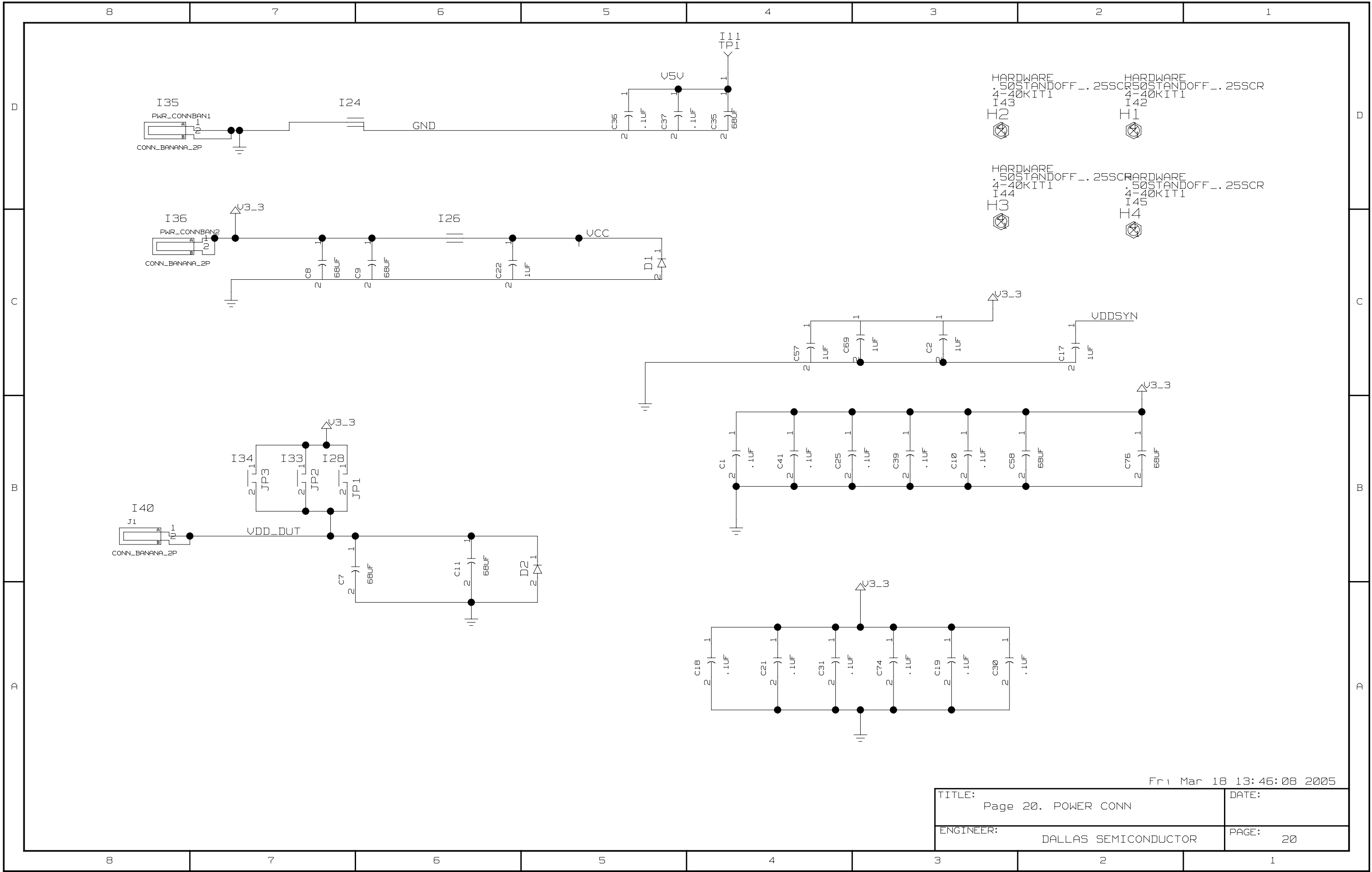
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TITLE:	Page 18. ADDRESS/DATA HEADERS	DATE:	
ENGINEER:	DALLAS SEMICONDUCTOR	PAGE:	18



Fri Mar 18 13:46:08 2005

TITLE: Page 19. MICROCONTROLOR SRAM	DATE:
ENGINEER:	PAGE: 19



HARDWARE .50STANDOFF..25SCR
 4-40KIT1 I43
 HARDWARE .50STANDOFF..25SCR
 4-40KIT1 I42
 HARDWARE .50STANDOFF..25SCR
 4-40KIT1 I44
 HARDWARE .50STANDOFF..25SCR
 4-40KIT1 I45

Fri Mar 18 13:46:08 2005

TITLE: Page 20. POWER CONN	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 20

8

7

6

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2

1

D

D

DESIGN NOTES:

1. 1/20/05 DESIGN / LAYOUT COMPLETED AND ARCHIEVED

C

C

B

B

A

A

Fri Mar 18 13:46:09 2005

TITLE: Page 21. NOTES	DATE:
ENGINEER: DALLAS SEMICONDUCTOR	PAGE: 21

8

7

6

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1

